

Integrated DC-DC Converter Design

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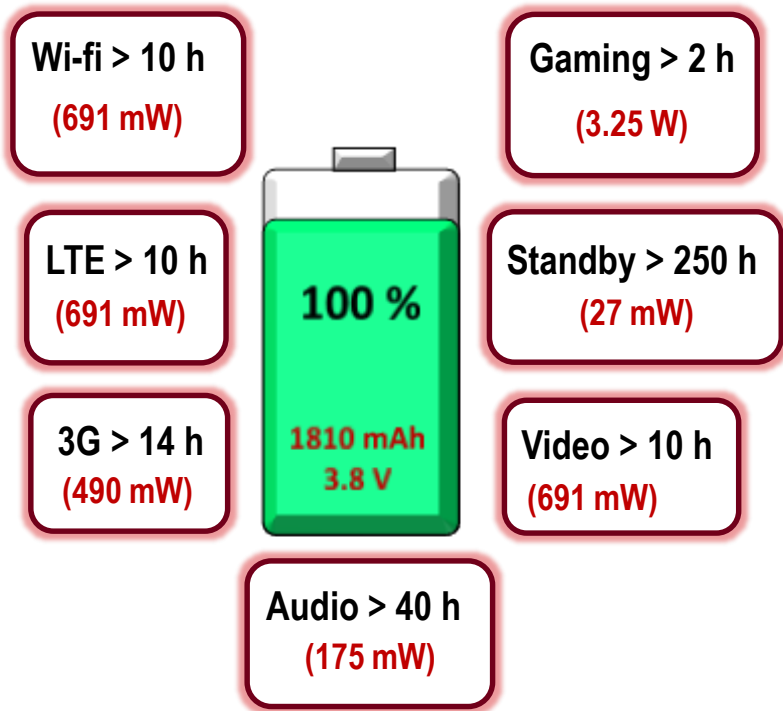
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Talk Outline

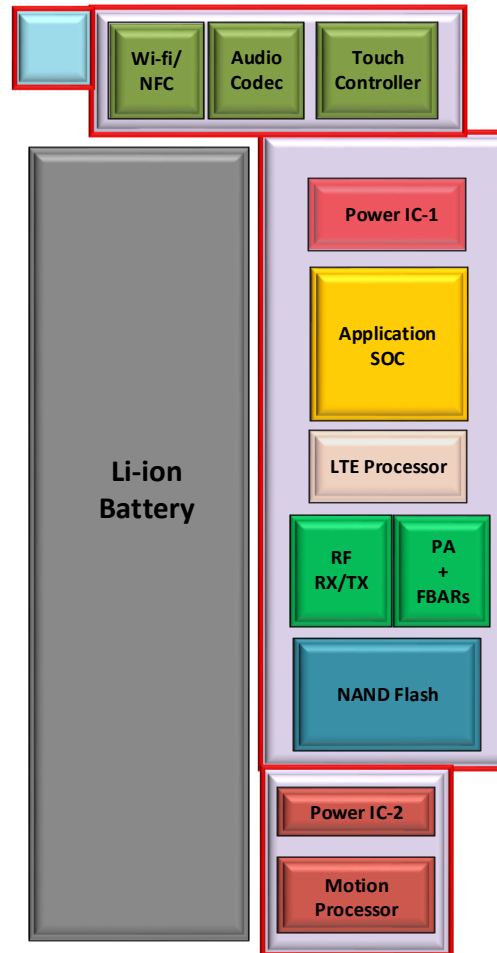
- **Introduction to DC-DC converters**
 - Motivation, uses
- **Types of DC-DC**
- **Linear converters**
 - Series/shunt
 - Classification, design
- **Inductive converters**
 - Passives + integration
 - Control, design methodology
 - Examples, SIMO
- **Capacitive converters**
 - Framework
 - Design methodology
 - Control, circuits
- **Special capacitive converters**
- **Design example - capacitive**

MOTIVATION

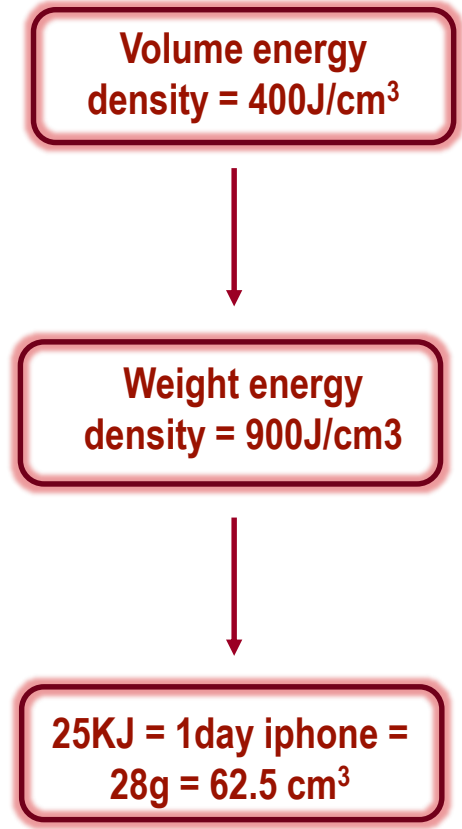
Power Is Precious



1 battery → Multiple features



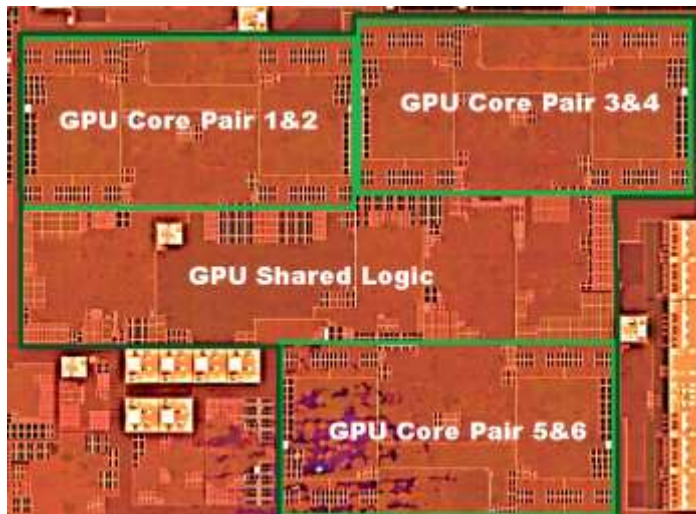
Smartphone teardown



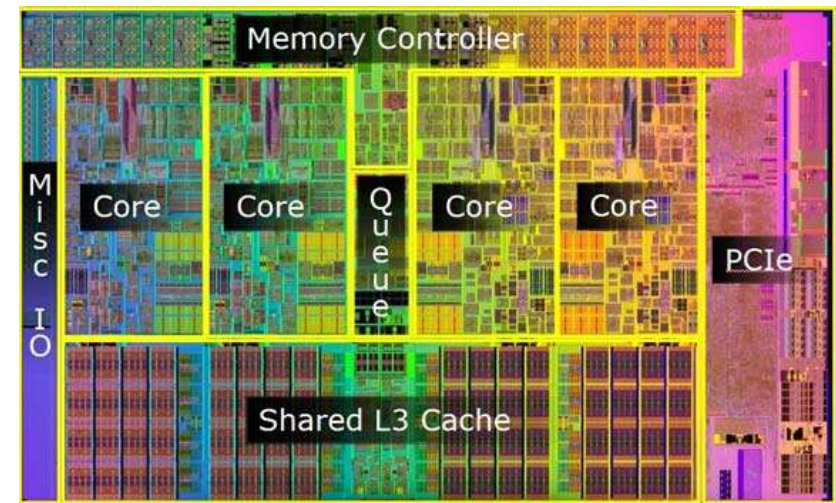
Motivation: Mobile Devices

- Rapid advancement in VLSI technology
 - Multi-core processors in battery powered devices
 - Si technology moved from 350nm in 1995 → 22nm NOW
- Battery capacity does not follow Moore's law
 - Li-ion battery energy density only 2X since 90s !!!! *

Apple A9 GPU core



Intel core i7 mobile



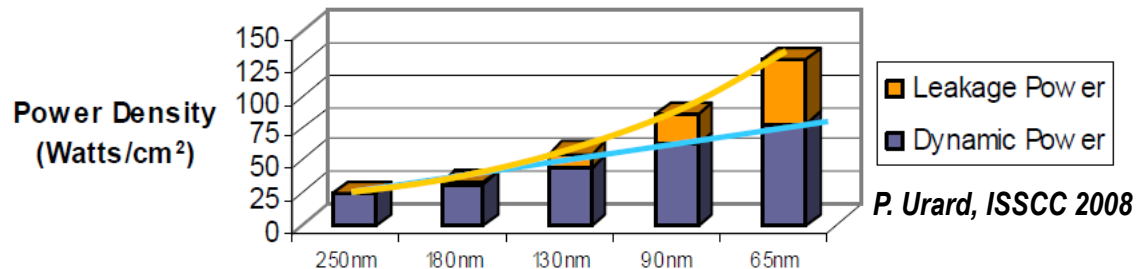
<http://www.anandtech.com/show/9686/the-apple-iphone-6s-and-iphone-6s-plus-review/5>

<http://hothardware.com/printarticle.aspx?articleid=1384>

Leakage Power & Multiple Domains

- Leakage power is an increasing contributor

ASICs [source: STMicroelectronics].

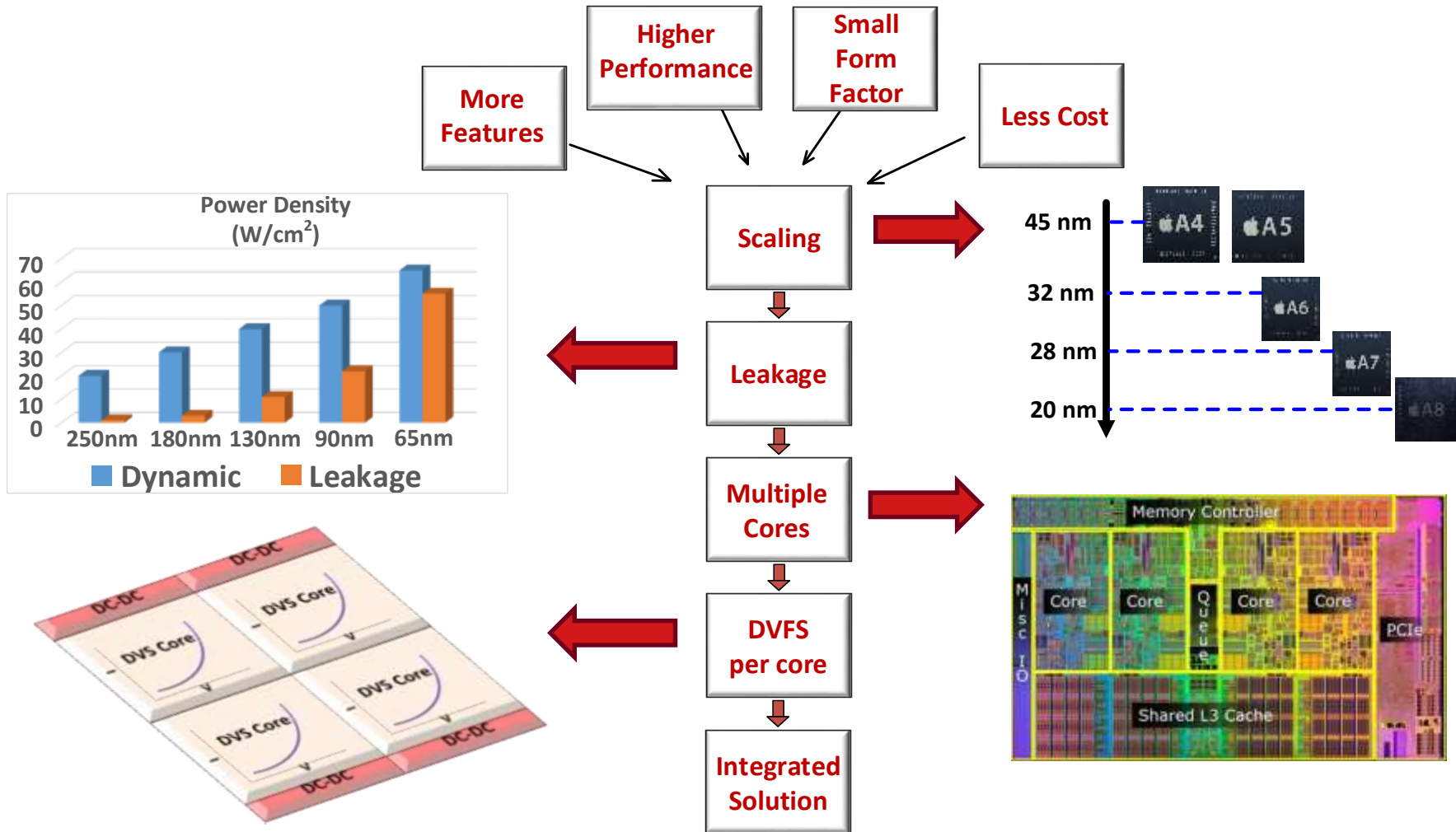


- Increase in the number of power domains



One-chip 3G Cellular Phone processor with 20 power domains, 90nm 8M, dual VT CMOS, Y. Kanno, et al, ISSCC 2006

Why Integration?



TYPES OF DC-DC CONVERTORS

DC-DC Converters Are Everywhere

■ Linear converters

- Low noise → no switching parts
- Efficiency depends on conversion ratio
- Primarily for down conversion (buck converter)

Ideally

$$P_{in} > P_{out}$$

■ Capacitor converters

- Buck, boost and voltage inversion possible
- Most popular switching converter
- Needs only capacitors & switches → easily integrated

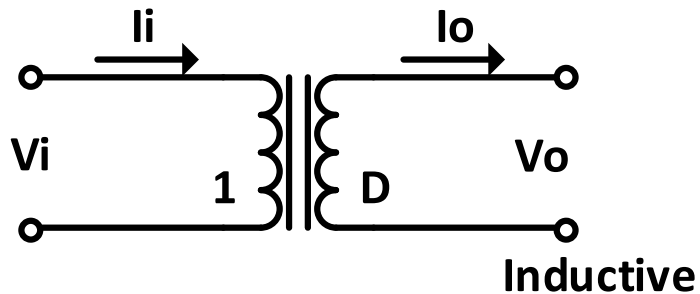
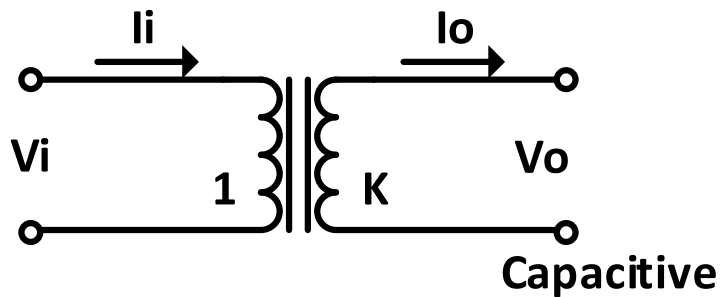
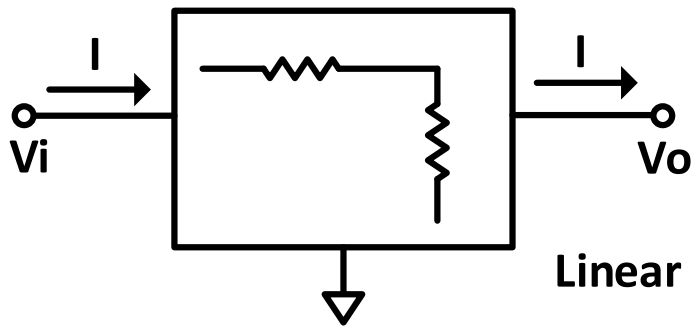
$$P_{in} > P_{out}$$

■ Inductive convertors

- Buck, boost and voltage inversion possible
- Theoretical high efficiency for any conversion ratio
- Need large, high-Q inductors → not easily integrated

$$P_{in} = P_{out}$$

DC-DC Converter Modelling (Ideal)



Transformer Model

1:1

1:k

1:D

Efficiency Voltage Relationship

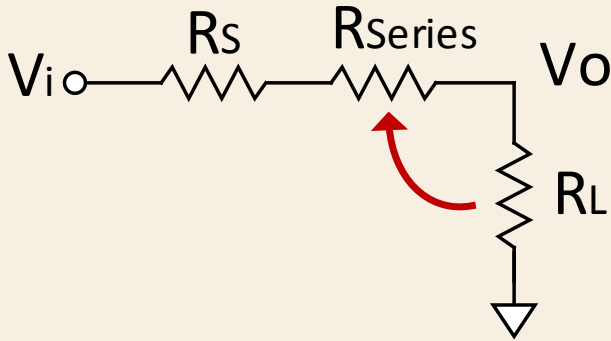
$$\eta = \frac{V_o}{V_i} ; V_o < V_i$$

$$\eta = \frac{V_o}{kV_i} ; V_o < kV_i$$

$$\eta = \frac{V_o}{DV_i} ; V_o = DV_i$$

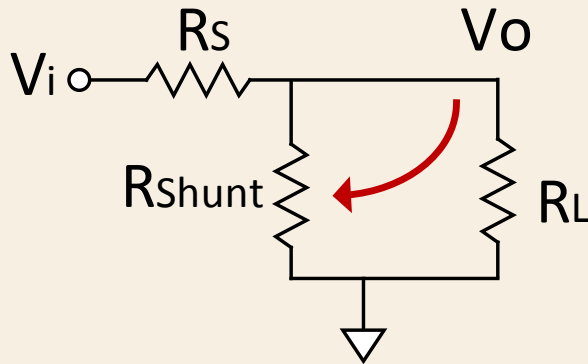
LINEAR CONVERTERS

Linear Regulators



$$\frac{V_o}{V_{in}} = \frac{R_L}{R_L + R_{Series} + R_s}$$

Series regulator

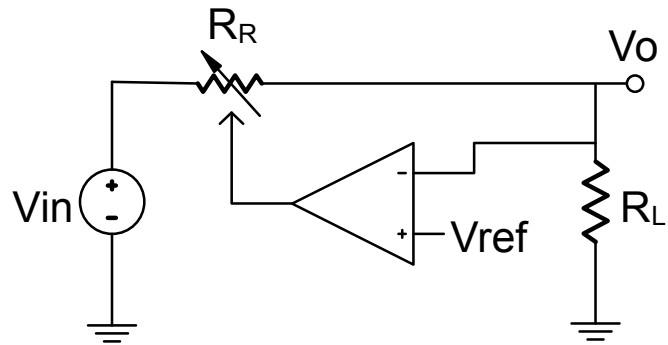


$$\frac{V_o}{V_{in}} = \frac{1}{1 + \left(\frac{R_s}{R_{shunt} \parallel R_L} \right)}$$

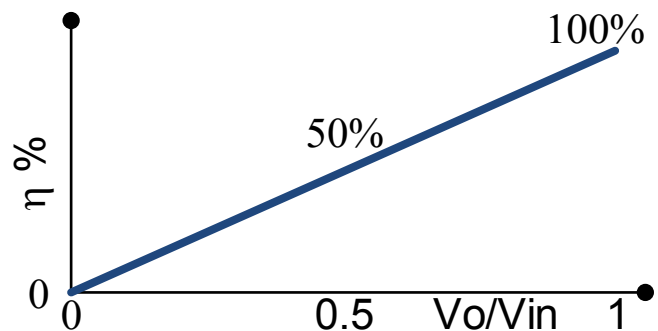
Shunt regulator

Series Regulator

- The output voltage V_o is kept constant by varying R_R
- Efficiency = power in load / power from source
- If same current is flowing in R_R and R_L then $\eta = V_o / V_{in}$



Linear Converter Block Diagram



Conversion Efficiency vs V_o/V_{in}

$$\eta = \frac{V_o^2}{R_L} \frac{R_R + R_L}{V_{in}^2} = \left(\frac{V_o}{V_{in}} \right)^2 \frac{R_R + R_L}{R_L}$$

$$= \left(\frac{R_L}{R_R + R_L} \right)^2 \frac{R_R + R_L}{R_L} = \boxed{\frac{V_o}{V_{in}}}$$

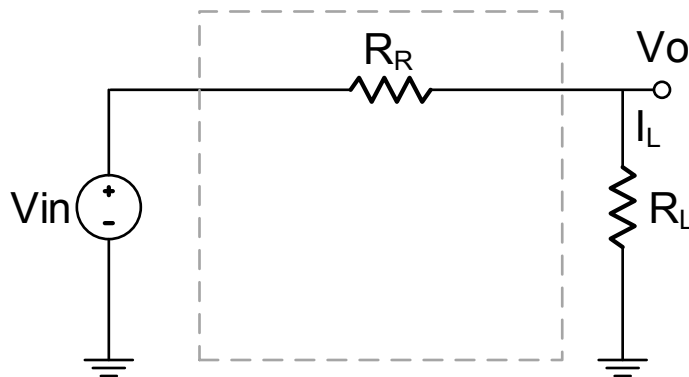
$$\eta = \frac{I_L \cdot V_o}{I_L \cdot V_{in}} = \frac{V_o}{V_{in}}$$

Voltage divider → efficiency is ratio of voltages

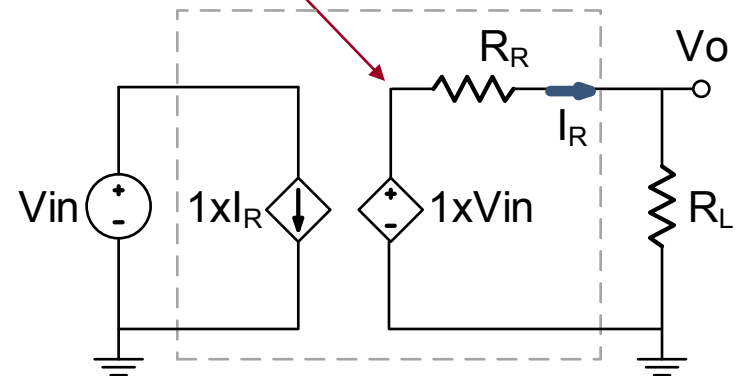
Model For Linear Converter

- Linear regulator = linear converter = aka LDO
- Linear regulator model \leftrightarrow transformer model
- Transformer has a turns ratio of 1
- Conversion efficiencies

$$\eta = \frac{V_o}{1 \times V_{in}} = \frac{V_o}{V_{in}}$$



Linear Converter Model



Linear Converter Transformer Model

Characteristics

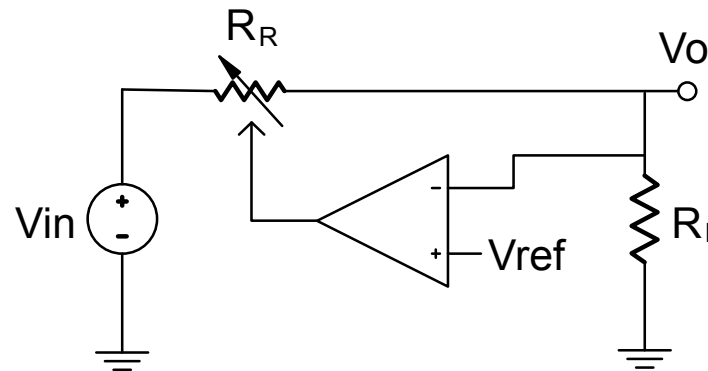
■ DC characteristics

- Line regulation

$$\frac{\Delta V_o}{\Delta V_{in}} = \frac{1}{1 + \beta A}$$

- Load regulation

$$\frac{\Delta V_o}{\Delta I_o} = \frac{R_{o,open}}{1 + \beta A}$$



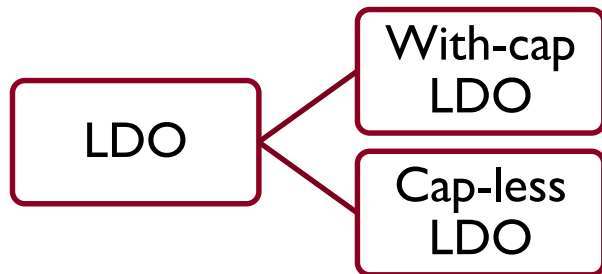
$$\beta = \frac{R_L}{R_L + R_R}$$

■ AC characteristics

- Input ripple rejection (PSR) → AC equivalent of line regulation
- Output ripple rejection → AC equivalent of load regulation

Low Drop Out Regulator

- Low Drop Out (LDO) regulator
 - $(V_i - V_o)$ is desired as low as possible
 - Most popular/researched topology



- With Cap LDOs
 - Off-chip output capacitor, higher power levers, discrete
- Cap-Less LDOs
 - Integrated, fast/higher bandwidth, large load transient droop



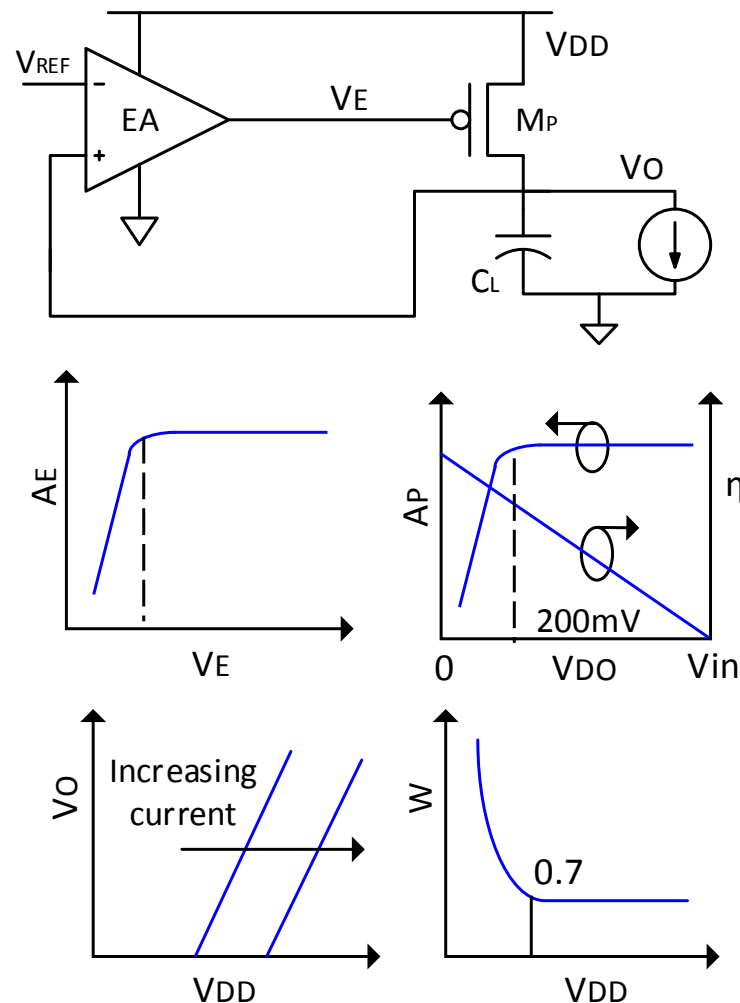
With-Cap LDOs

■ With Cap LDOs

- Output capacitor, C_L , is the dominant pole capacitor
- Small bandwidth, less droop
- Easy compensation

■ Design constraints

- V_E cannot be lower than a ΔV
- $V_{o,max} = V_{DD} - \Delta V$
- AE, AP must be constant during the operation of regulation
- Width of the pass transistor goes up rapidly for lower VDD



Compensation

■ Dominant pole

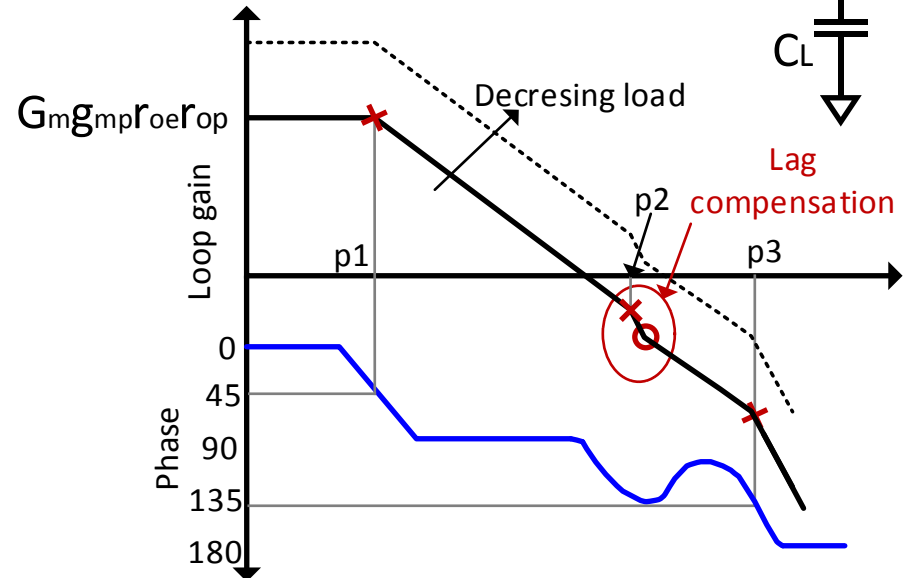
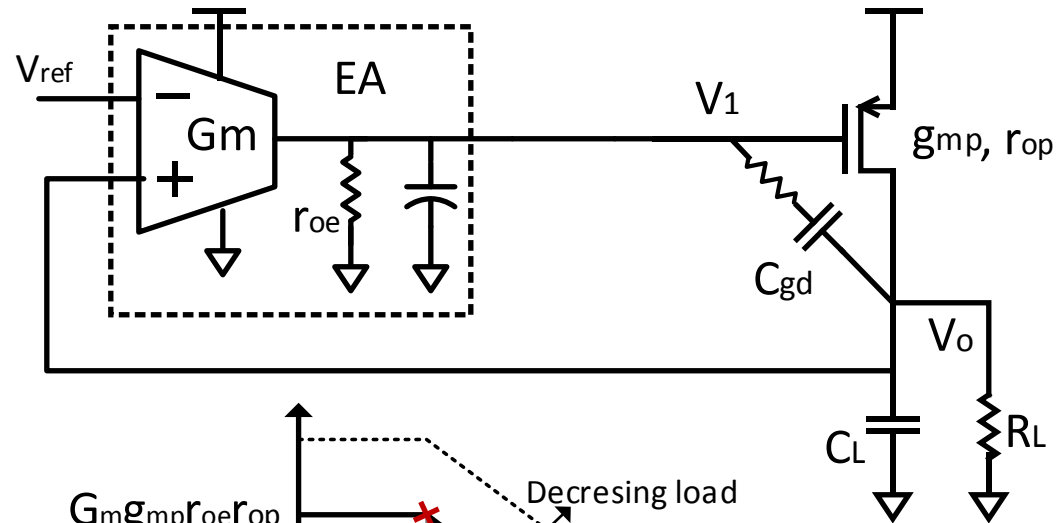
- Output capacitor, C_L , is dominant pole capacitor
- Small bandwidth, Easy compensation

■ Non dominant poles

- EA internal poles
- Gate of the pass transistor

■ Impact of load

- More instability at lighter load



CAP-Less LDOs

■ Dominant pole

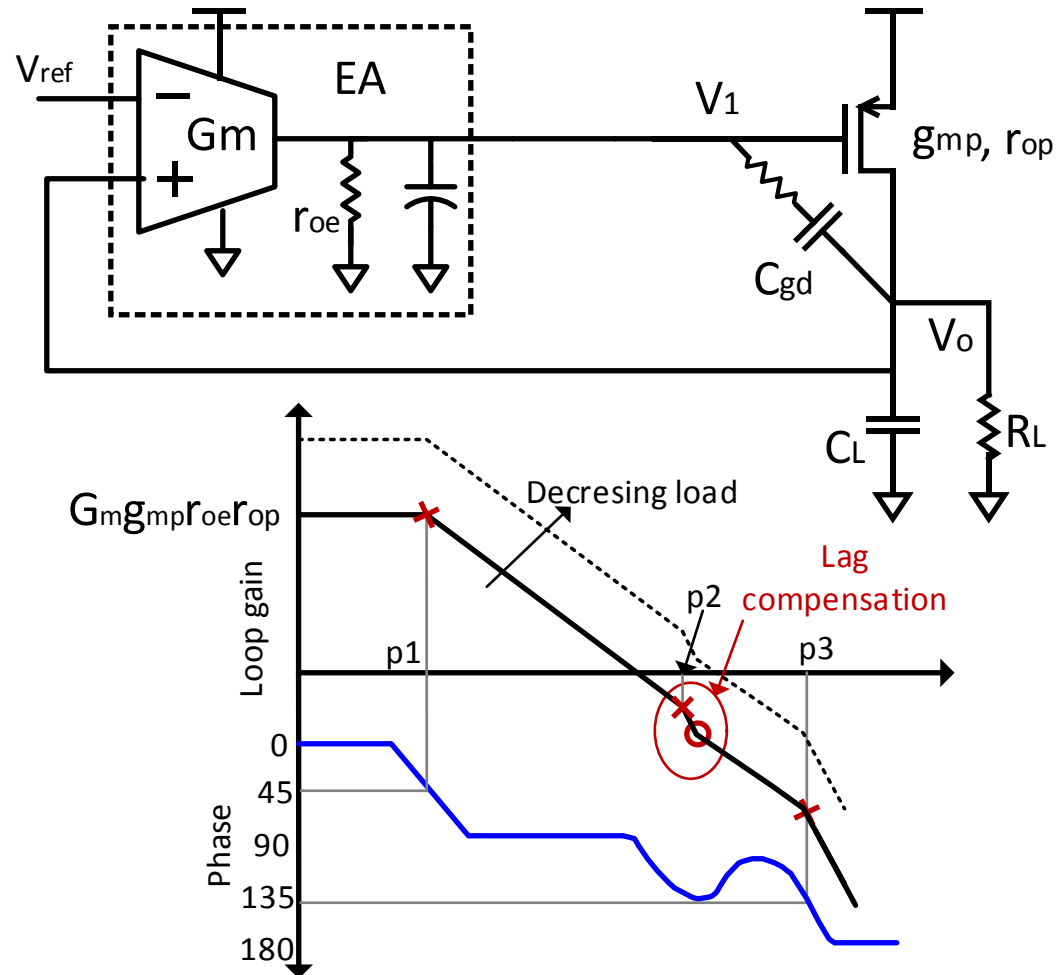
- Dominant pole of the EA
- Large bandwidth, difficult compensation

■ Non dominant poles

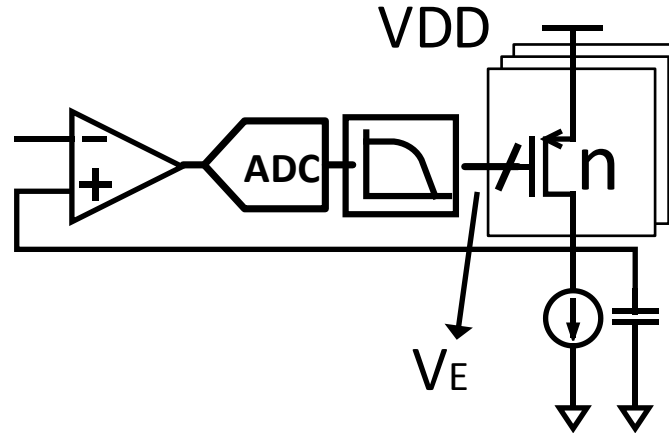
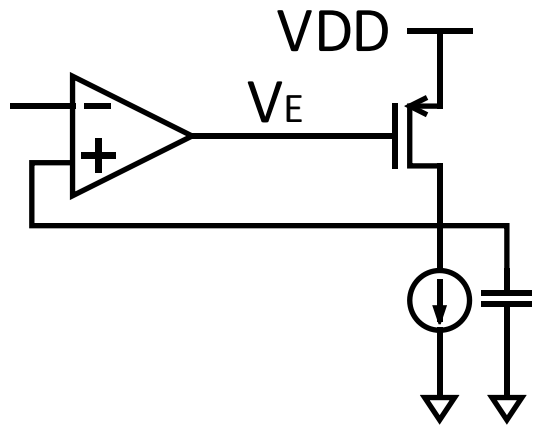
- Gate of pass transistor
- EA internal poles

■ Impact of load

- More instability at lighter loads as gain increases



Classification



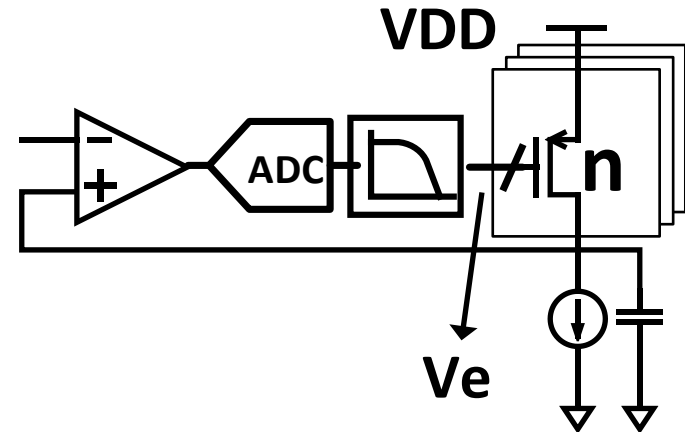
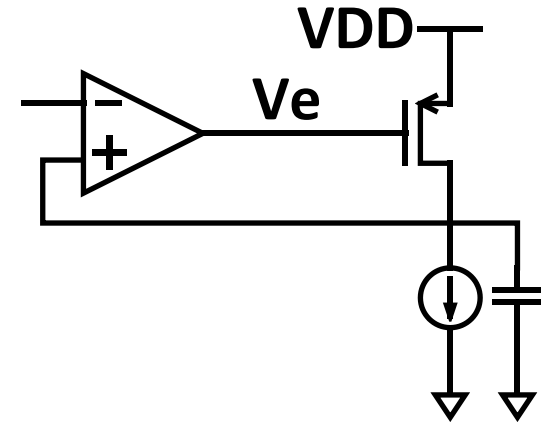
- Analog amplitude
 - No steady state output ripple
 - Analog compensation
- Digital amplitude
 - Steady state ripple
 - Digital compensation

Conventional LDOs

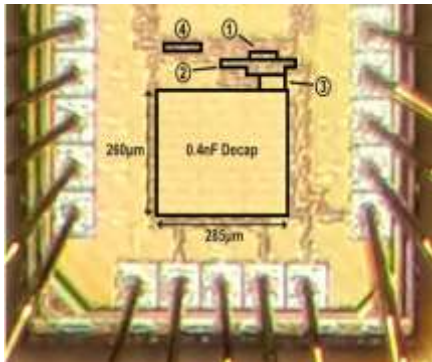
Digital LDOs

Digital LDOs

- Motivation - analog vs digital
 - As VDD lowers, V_e is bottleneck
 - Make V_e zero
- DLDOs
 - Pass transistor either OFF/ON
 - Mimic LDO operation
 - Complex design
 - Easy compensation
 - Intrinsic ripple due to quantization

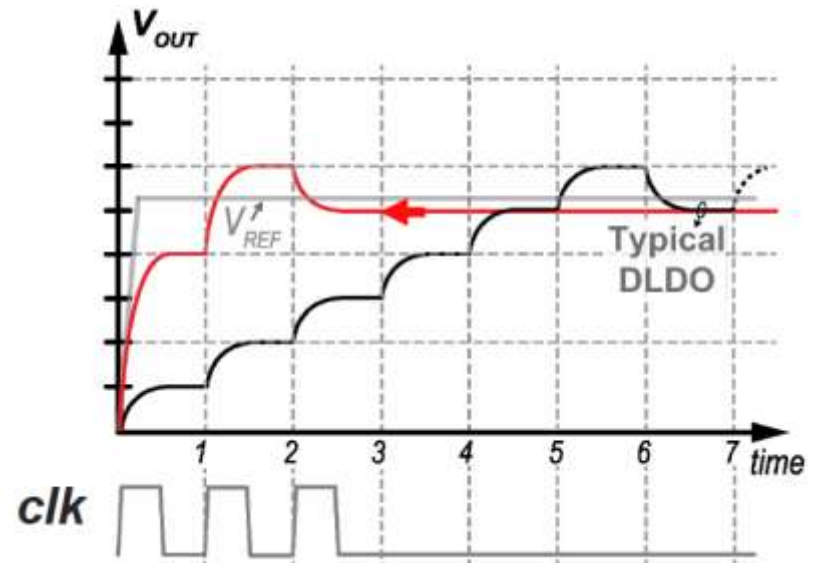
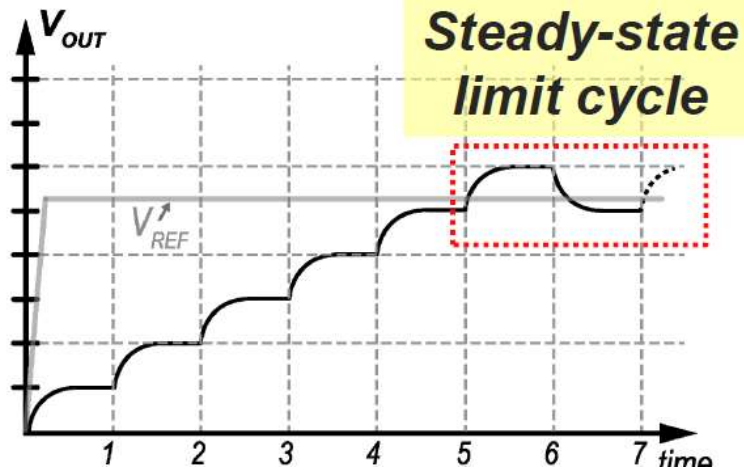
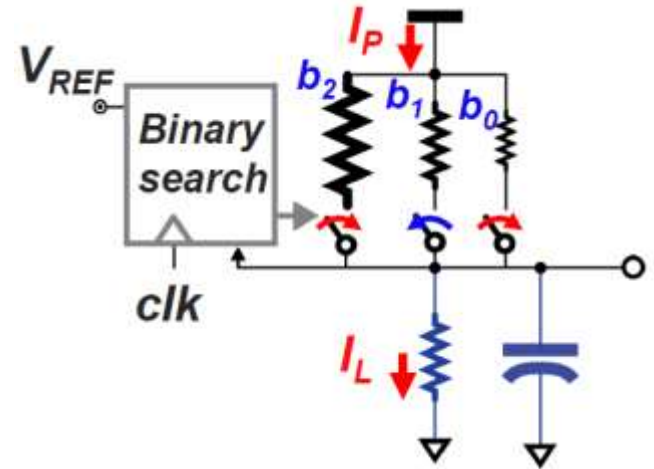
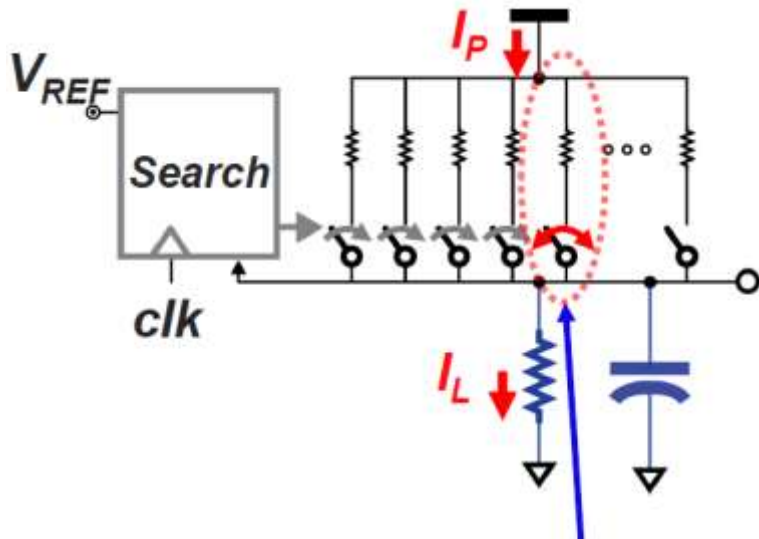


A 100nA-to-2mA SAR DLDO With PD Compensation And Sub-LSB Duty Control



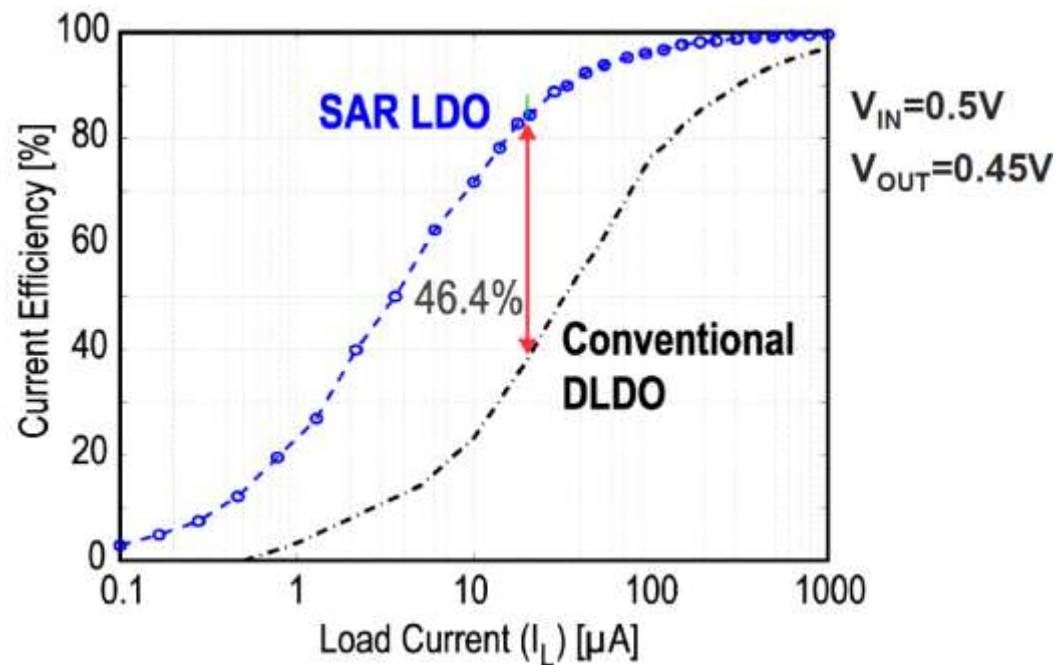
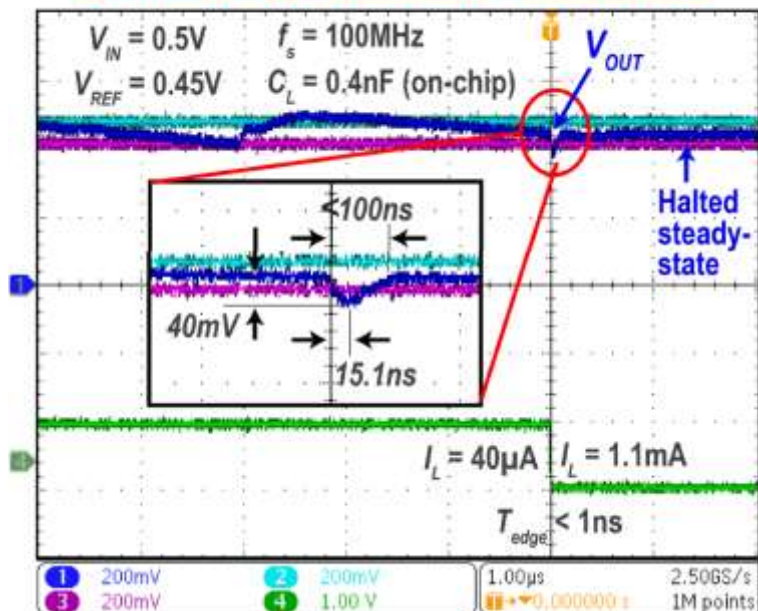
Process: IBM 130nm CMOS
Loai G Salem, Patrick Mercier
ISSCC 2017

Example - SAR DLDO



Measurement Results

Measured voltage droop: 40mV



	Proposed LDO	Prior LDO
Response time (T_R)	15.1ns	377.5ns
Settling time	<100ns	1.37µs
FOM	199.4ps	638ns

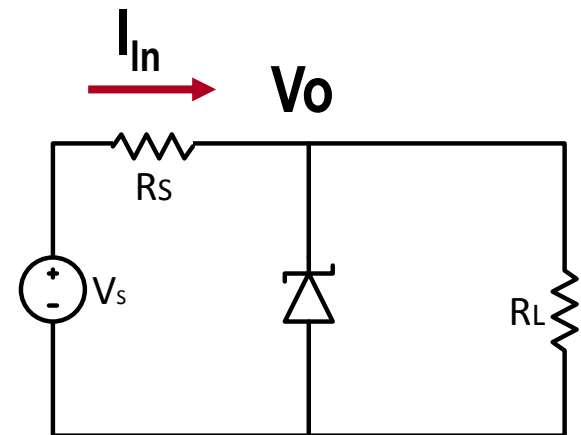
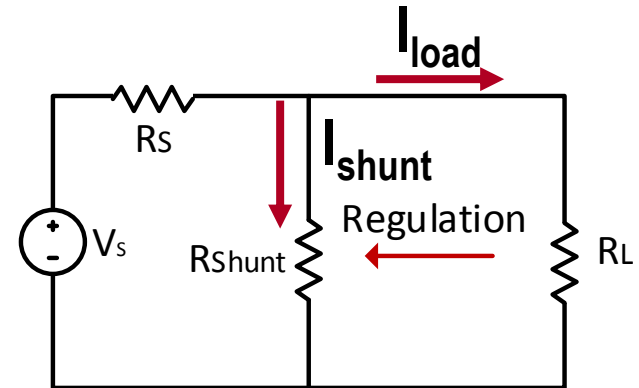
$>2^{2N}/N$



Shunt Regulator

■ Motivation

- Lowest operating point (Minimum $V_{in}-V_o$)
- If power supply is high ($|V_{in}|$ is high)
- Good for making
 - Negative reference
 - Floating reference
 - Voltage limiting reference
- Unequal input and output currents
- Shunt resistor regulates
- Less popular (bulky)



Current divider \rightarrow efficiency is ratio of currents

$$\eta = \frac{I_{Load}}{I_{in}} = \frac{1}{1 + \frac{I_{Shunt}}{I_{Load}}}$$

INDUCTIVE CONVERTER

Inductive Power Converter

■ Switch

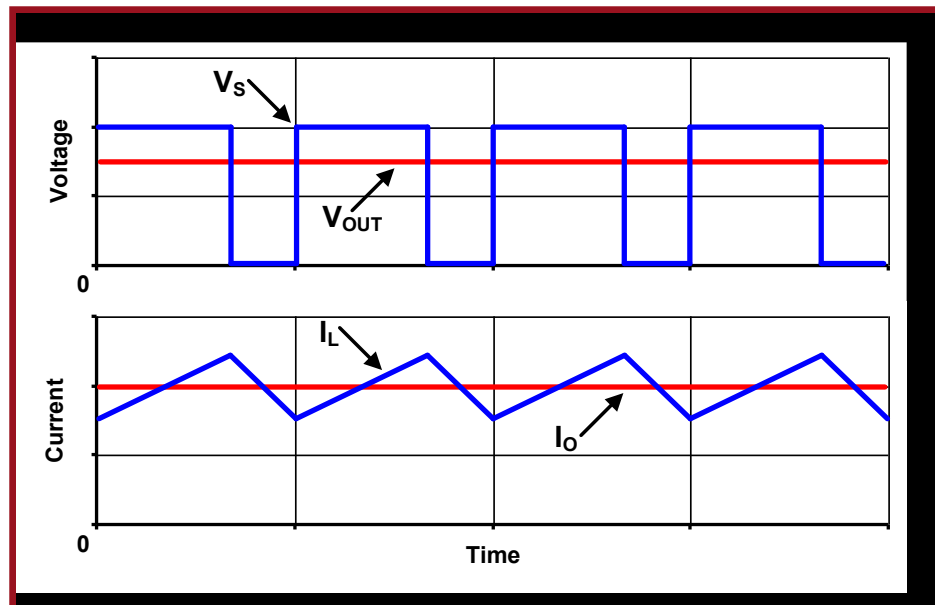
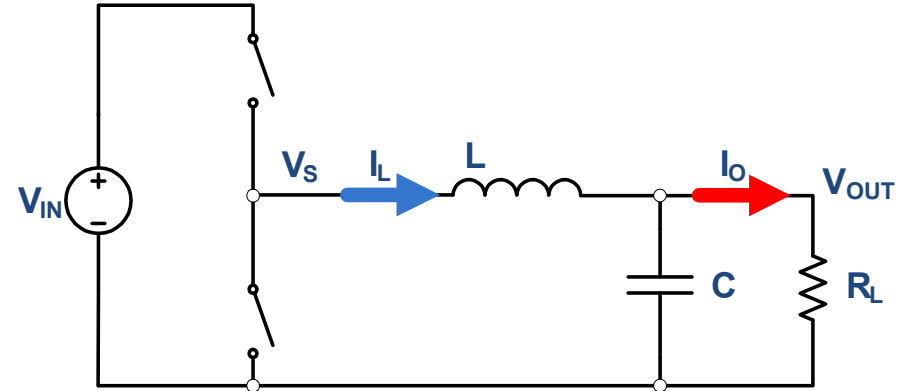
- Chops up the input voltage
- Can be implemented using a Diode-FET, NMOS-PMOS, or NMOS-NMOS combinations

$$V_{out} = D \cdot V_{in}$$

■ Filter

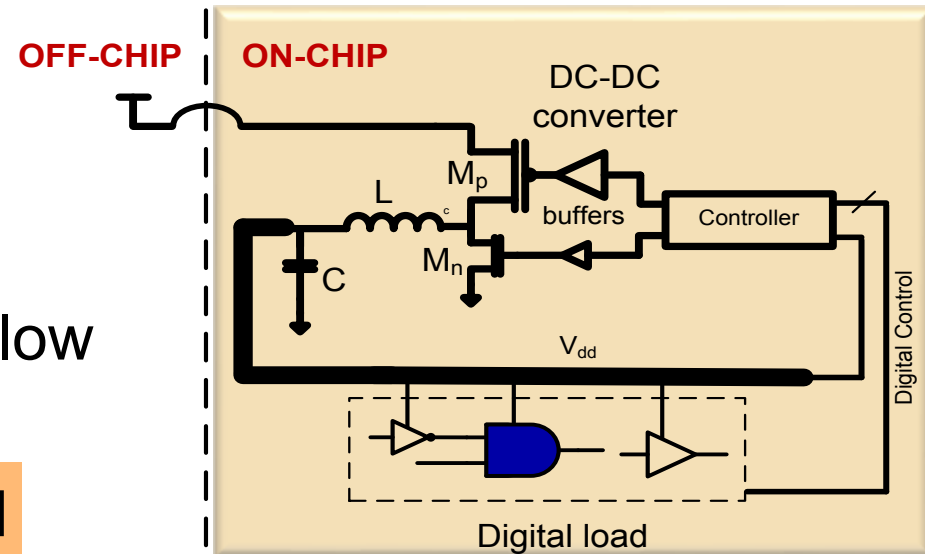
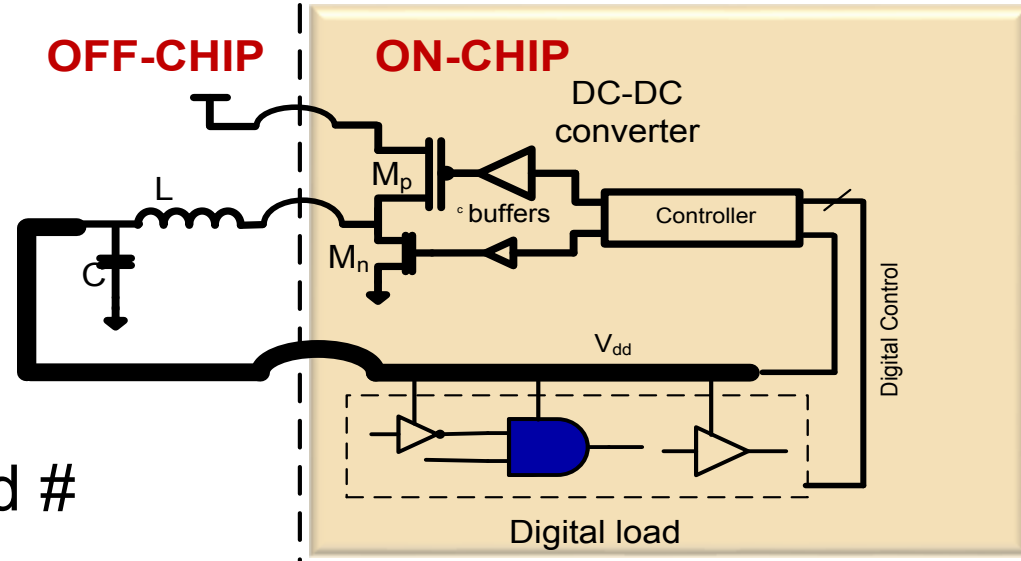
- Ripple current is proportional to switching frequency and inductance
- Ripple voltage is proportional to ripple current and output capacitance

$$I_{ripple} = \frac{1}{L} V_{in} \cdot D(1 - D) \frac{1}{f}$$



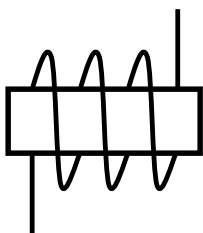
Why Fully Integrated Converters ?

- Passives off-chip
 - ✓ Large L and C possible
 - ✓ Good quality of L and C
 - ✗ Higher BOM
 - ✗ Large pin-count
 - ✗ Power domains → limited #
- Fully integrated converter
 - ✓ Small pin count
 - ✓ Lowest BoM
 - ✓ Power domains → large #
 - ✗ Small L and C , Quality of L low
 - ✗ Consumes silicon area
- Goal: reduce on-chip overhead

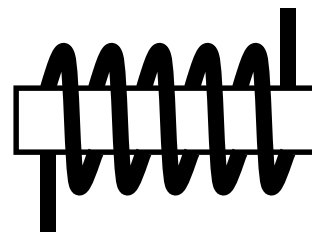


Integration - Inductors

- Output filters require high inductance ($1\mu\text{H}$ to $100\mu\text{H}$)
- High inductance results in
 - Large area
 - High series resistance resulting in low efficiency
- 1-3nH integrated inductors have reasonable series resistances
- Low inductance generates large current ripple resulting in
 - Large output voltage ripple
 - Low efficiency

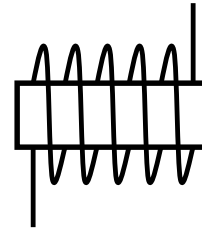


Increasing Inductance



■ Strategy for integration

- **Interleaving**: makes output independent of inductor current ripple
- **Magnetic coupling**: reduces current ripple magnitude at inductor
 - On-chips are close and so have coupling



Increase Loss

OR

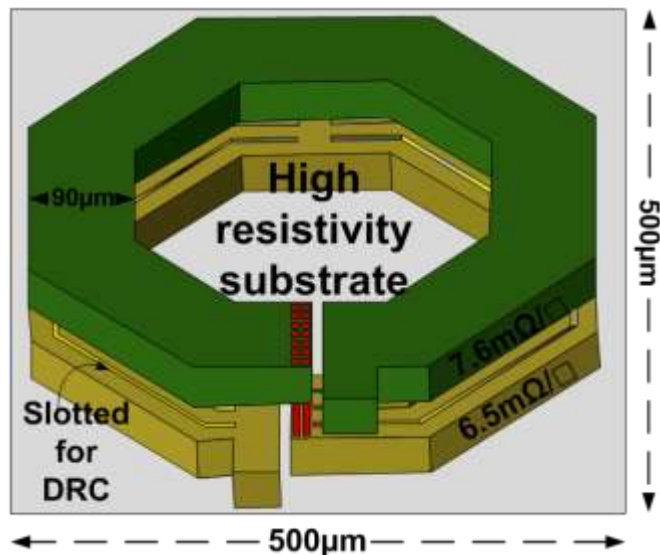
Increase Area

Inductors

■ Inductors

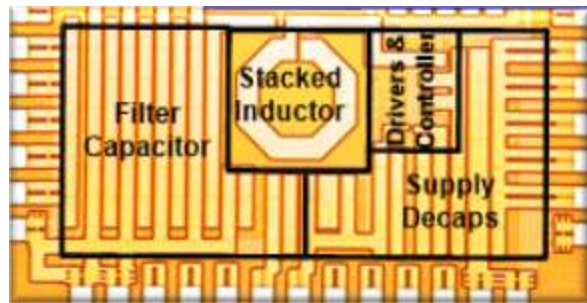
- Area bulky ($1\text{nH}/0.2\text{mm}^2$)
- High quality factor – a problem (typically $1\text{nH}/150\text{m}\Omega$)

■ Examples



- Diameter: $600\mu\text{m}$
- Metal Width: $75\mu\text{m}$
- Turns: 1.75
- Spacing: $4.5\mu\text{m}$

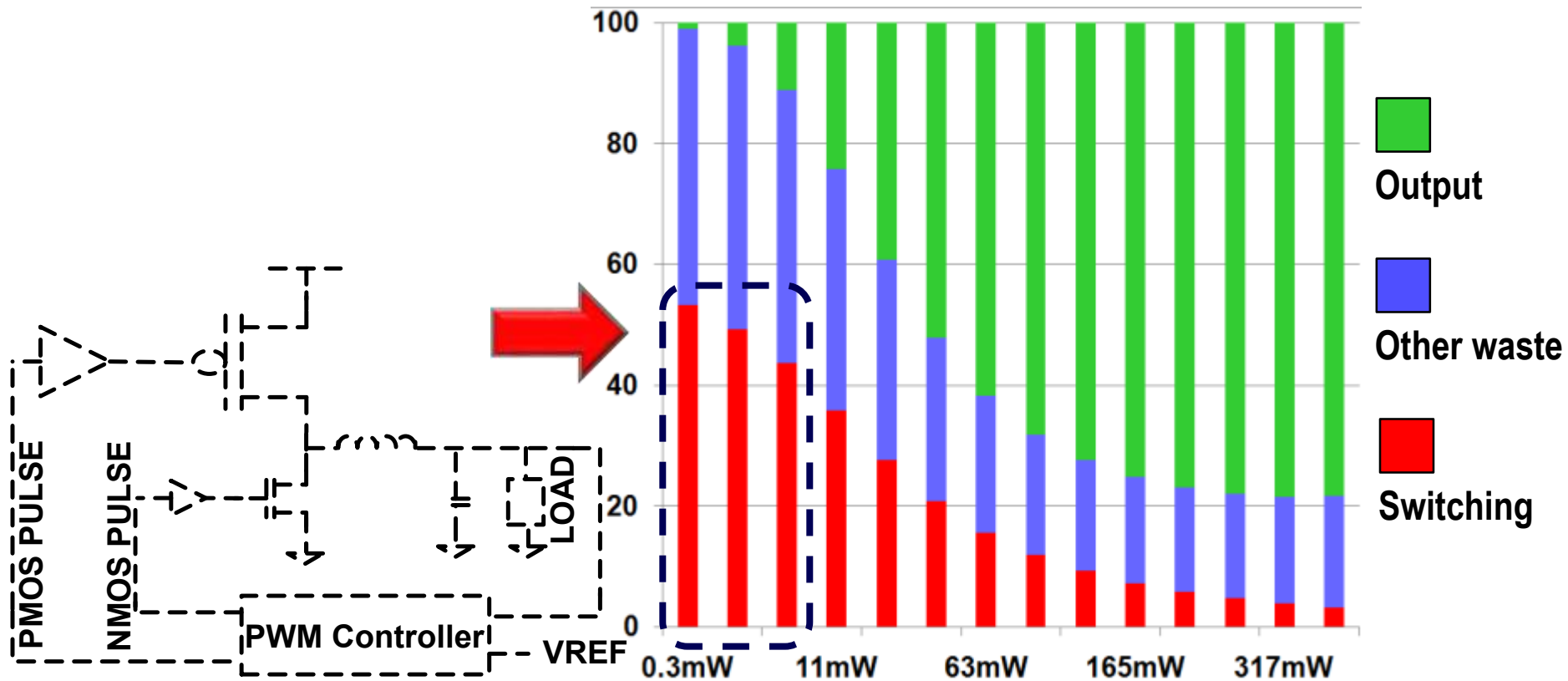
Fully Integrated On-Chip DC-DC Converter with a 450x Output Range



Process: IBM 130nm CMOS
Sudhir Kudva
CICC 2010, JSSC 2011

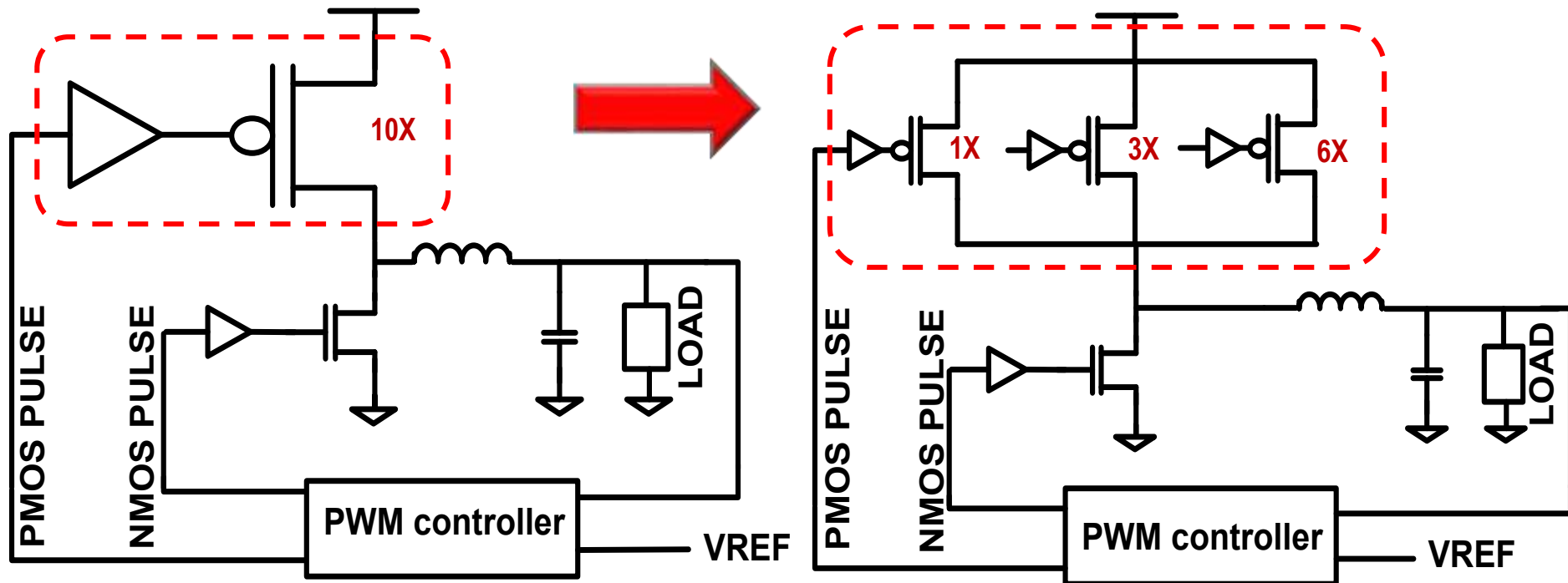
Typical Buck Converter

- Switching power significant % of wasted power @ lower currents



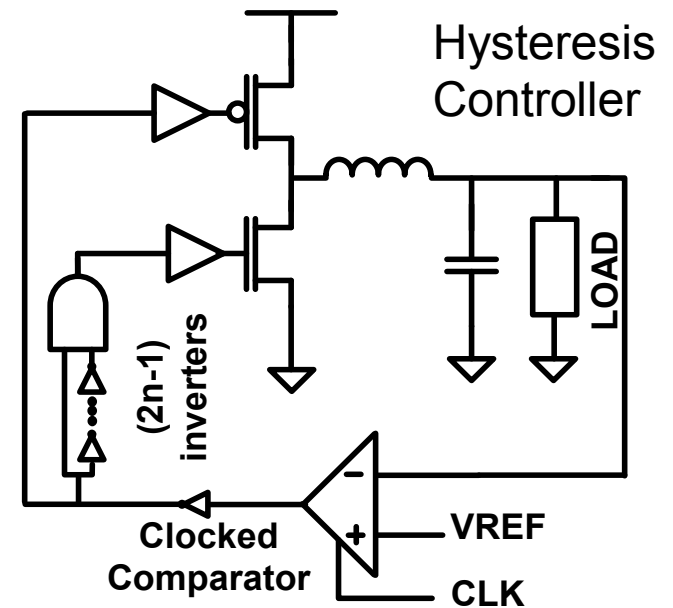
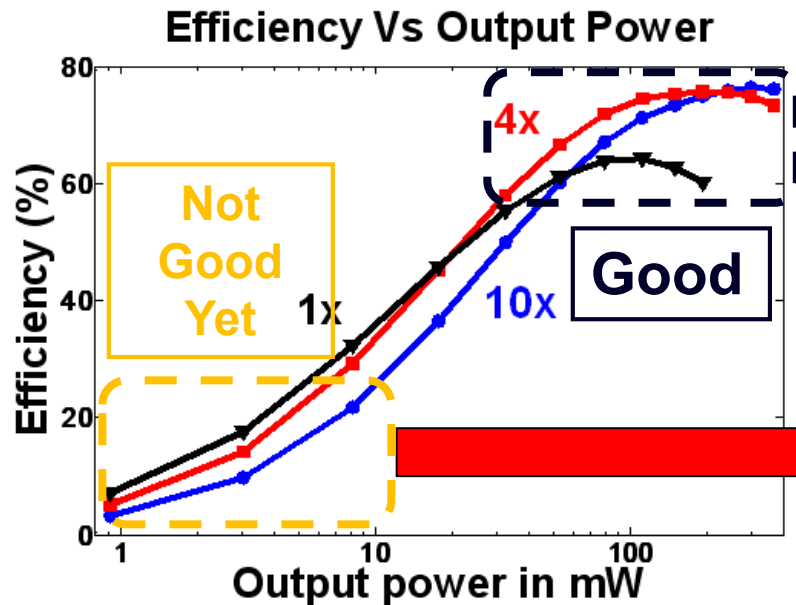
Modified Circuit

- Split PMOS switch and the drivers
- Size of the nail decides the hammer
- Only PMOS variable → larger PMOS to handle larger current



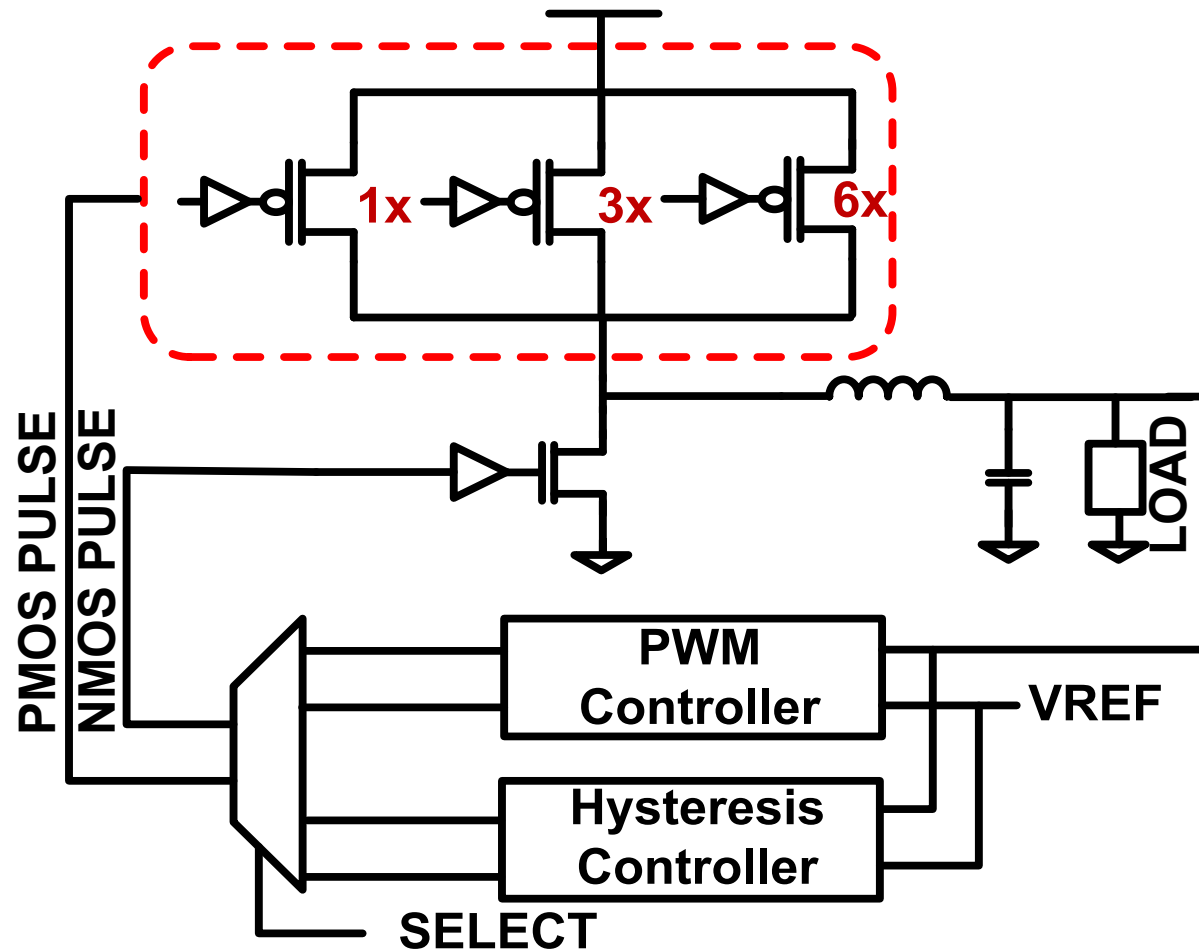
Hysteresis Controller

- Improved efficiency at high output loads
- However, still low efficiency at low loads
- Switch pulse frequency depend on the load current
- Effectively variable switching frequency
- PMOS and NMOS both OFF for some time



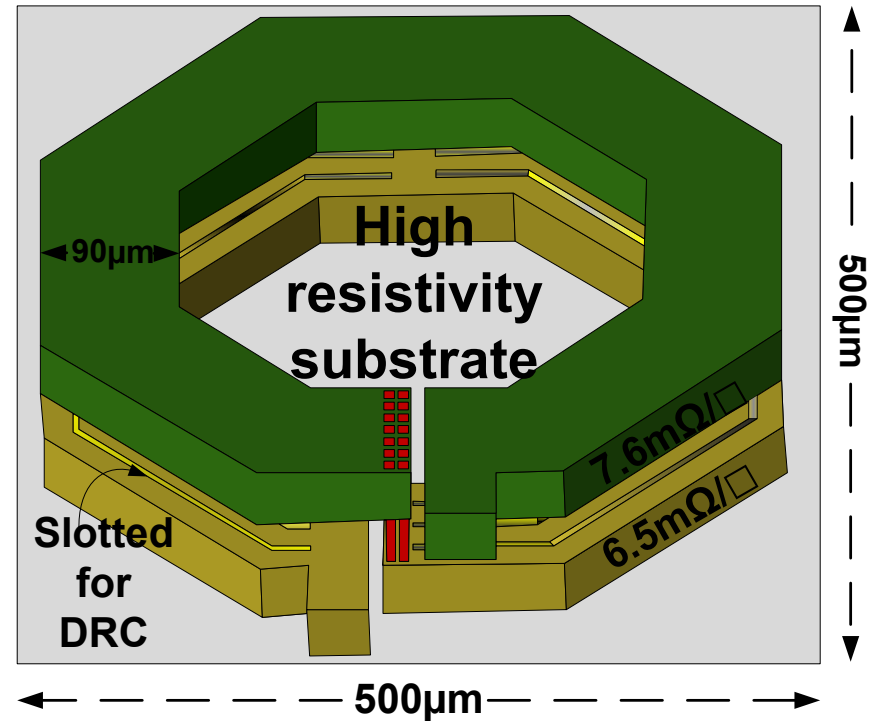
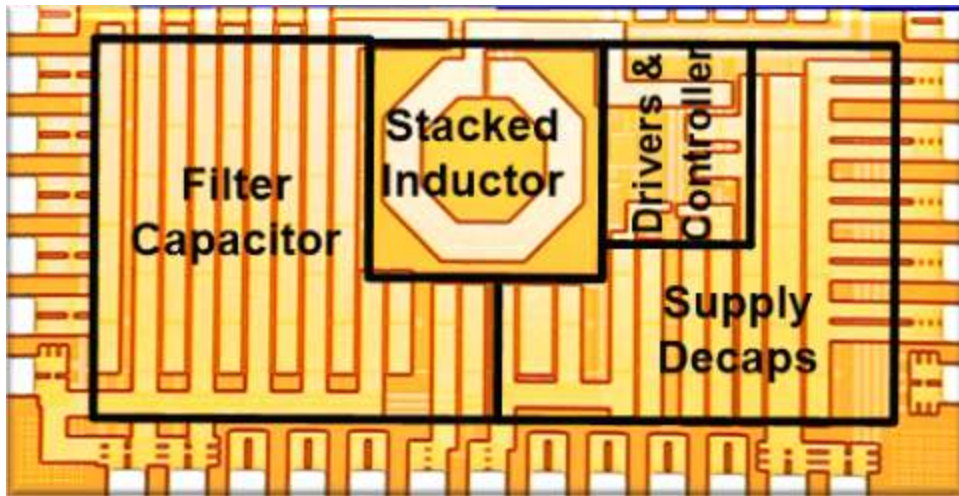
Integrated Converter

- Variable PMOS switches \rightarrow 10x, 4x, 1x
- High load \rightarrow PWM, Low load \rightarrow Hysteresis



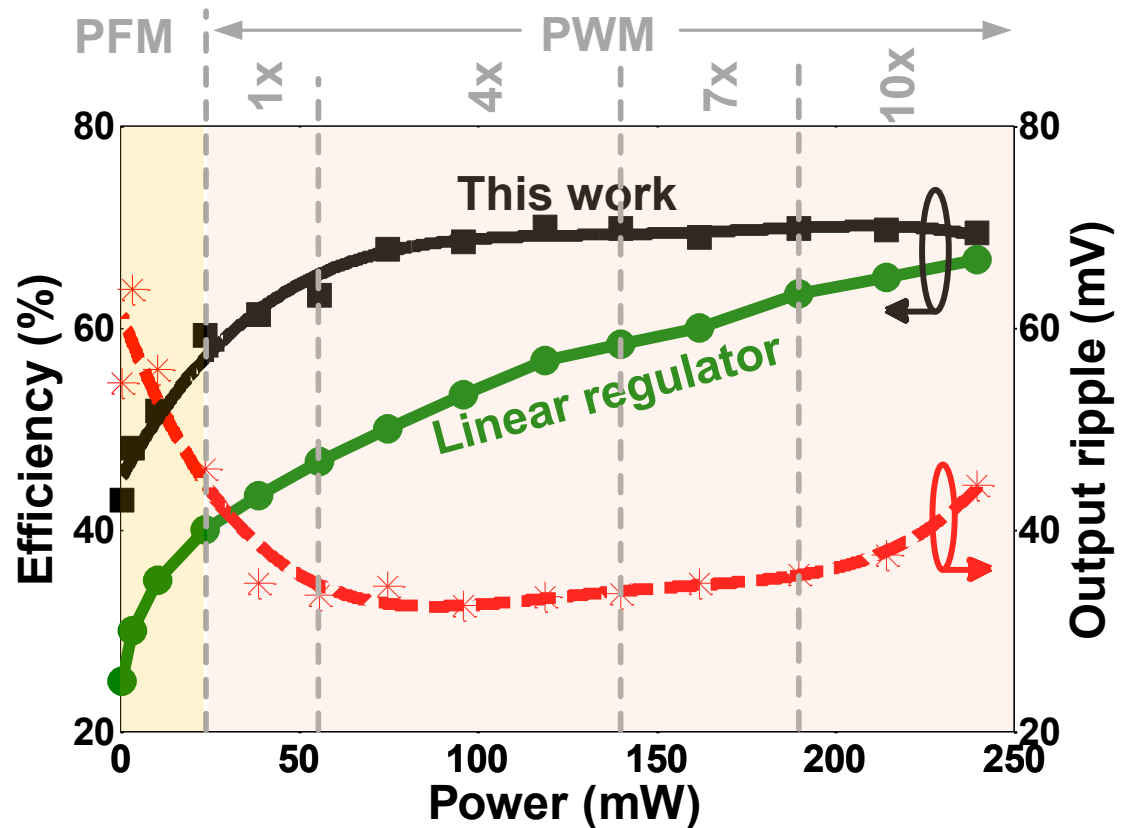
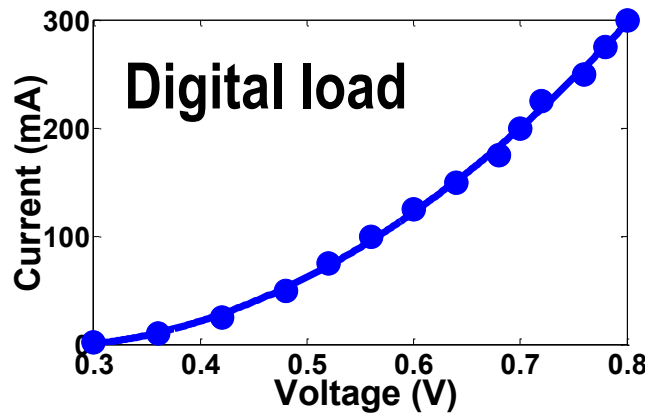
Chip Photograph

- IBM 130nm CMOS process
- Converter core area – 1.13mm²
- Total area with supply decaps – 1.592mm²
- Capacitance – 5nF Inductance - 2nH



Measurement Results: Efficiency

- Current increases quadratically with voltage
- Quadratic fit shown
- Efficiency is maximized at all loads by changing operating modes

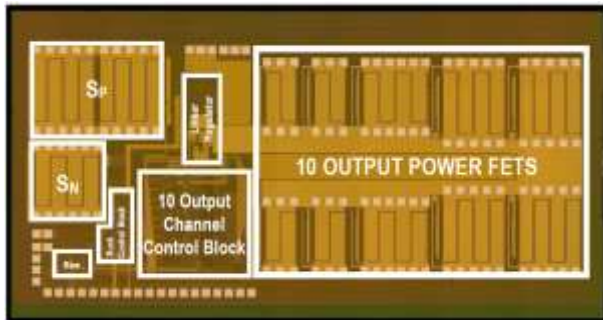


Inductive: Comparison

	O/P Power (mW)	O/P Power range	Efficiency (%)	Inductor/ Capacitor	Passive Components
Musunuri PESC 2005	50 – 200	~4X	40 - 60	0.1 μ H/30nF	MEMS inductor
Xiao JSSC 2004	0.15-600	~4000X	70 - 92	10 μ H/47 μ F	Off-chip inductor and capacitor
Wibben JSSC 2008	3 – 315	~100X	10 - 78	2x2nH/5nF	On-chip inductor and capacitor
Abedinpour T PE 2007	95 – 400	~4X	35 - 64	2x11nH/6nF	On-chip inductor and capacitor
This work	0.6–266	~450X	42.8 - 74.5	2nH/5nF	On-chip Inductor and capacitor

This work provides best on-chip performance

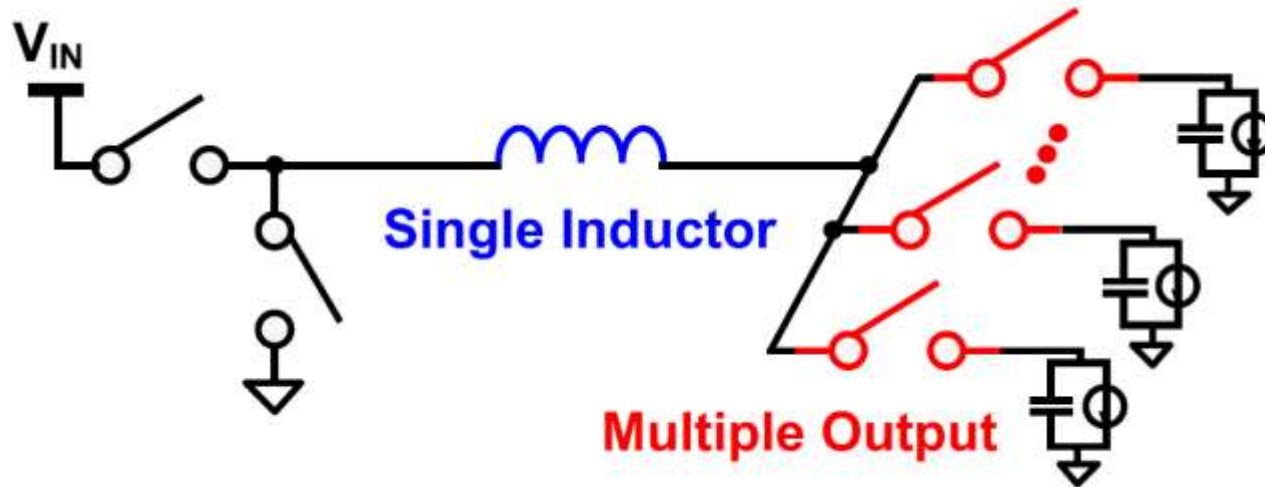
An Error Based Controlled Single Inductor 10 Output DC-DC Buck Converter with High Efficiency at Light Load



Process: 0.35um Process
Min-yong Jung
ISSCC 2015

Advanced Inductive Converter

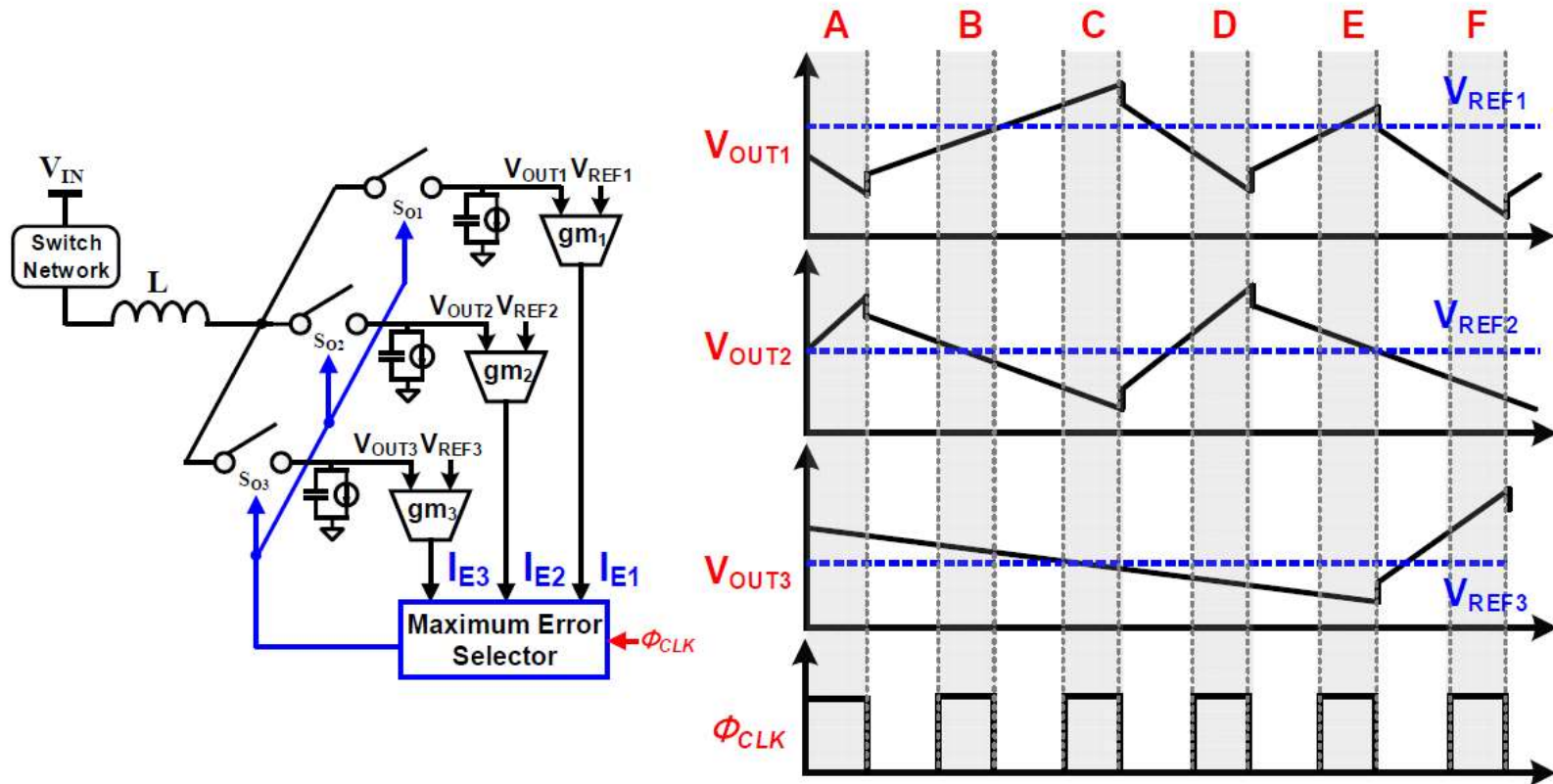
- Single Inductor Multiple Output (**SIMO**) inductive converter



- ◆ Problems
 - ✓ Cross Regulation
 - ✓ Large Ripple
 - ✓ Poor Efficiency at Light Load

Error Based Control

- Turning on the switch which has the largest error

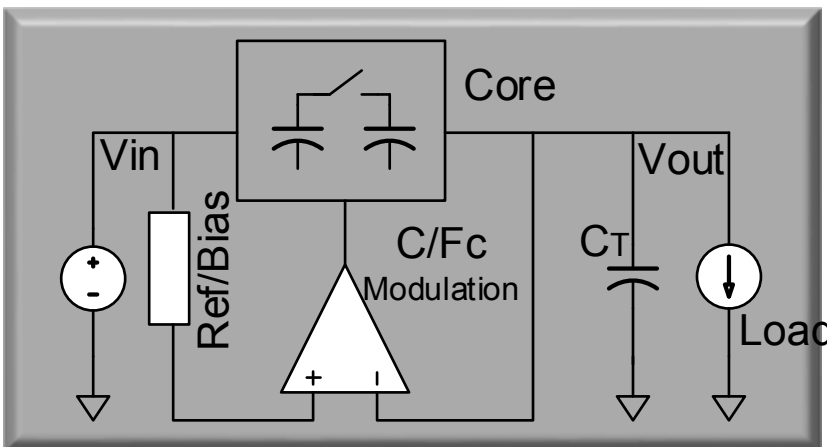


$\phi_{CLK} \rightarrow$ Error Compare \rightarrow Turn on the Switch (Max Error)

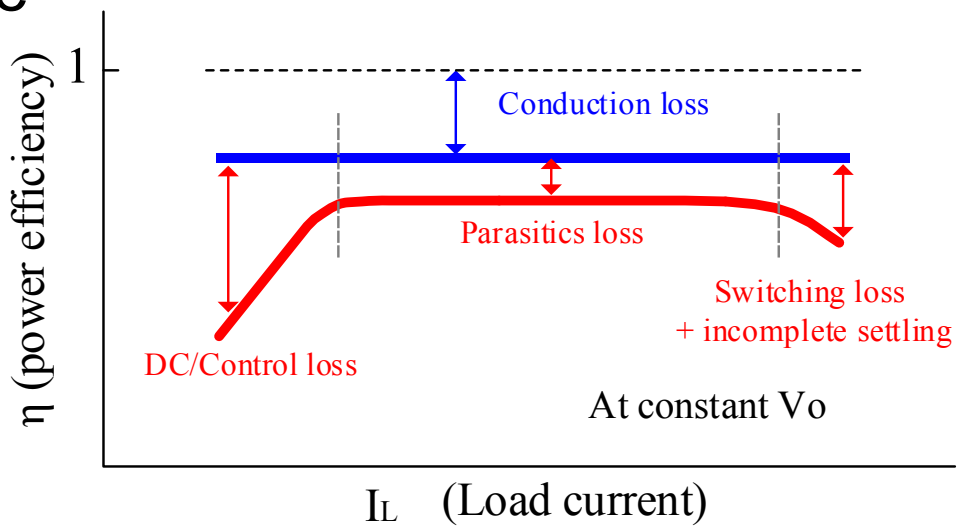
CAPACITIVE CONVERTER

Capacitive Conversion Efficiency Trends

- Conduction loss : Fundamental – sets upper limit
- Parasitic loss: sets peak value
- DC control losses: almost constant with load – dominate at lighter loads
- Partial charging loss: dominates at higher loads



Capacitive DC-DC converter

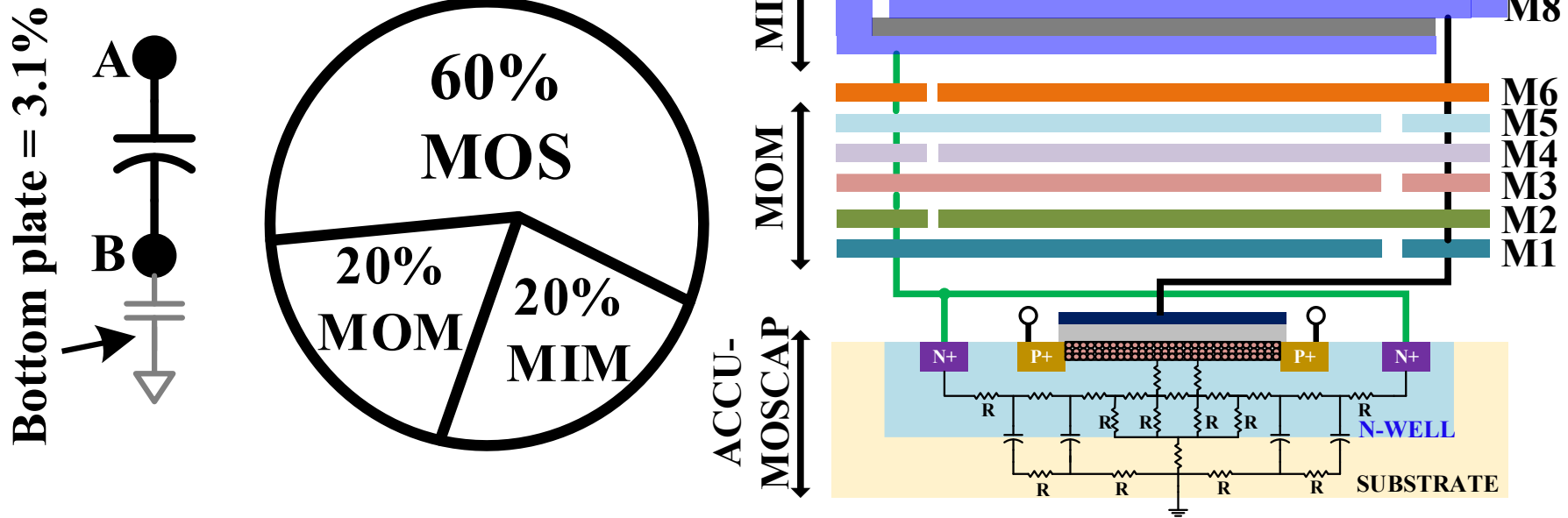


Present Day Integrated Capacitors

- Power density → capacitive density
- Desired qualities of integrated capacitor
 - Low bottom plate capacitance
 - High density, low leakage, low ESR
- MIM (Metal Insulated Metal)
 - Low density, low bottom plate parasitic, expensive
- MOM (Metal Oxide Metal)
 - High parasitic, low density, cheap
- MOS (Inversion)
 - High density, high leakage, medium bottom plate
- Floating Junction High Density Capacitor
 - Low Leakage, higher density

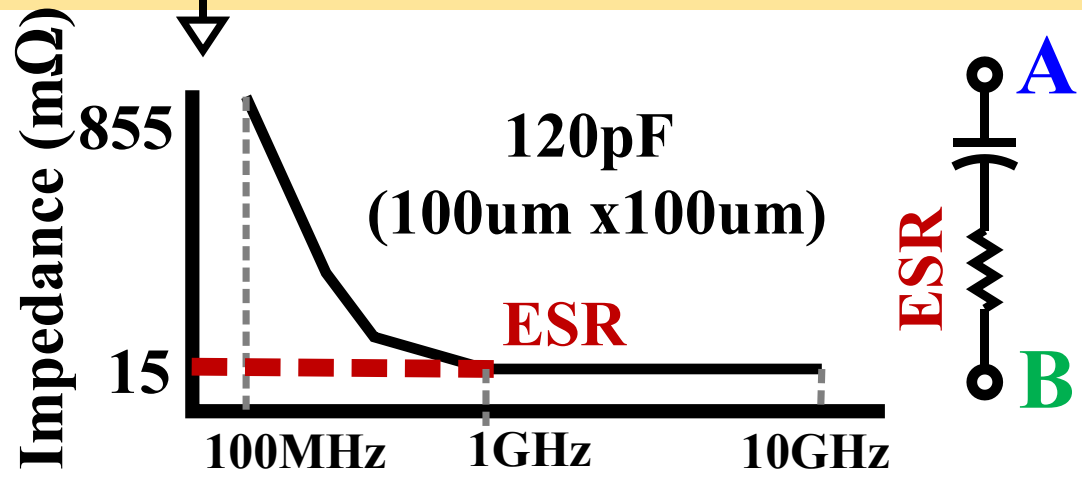
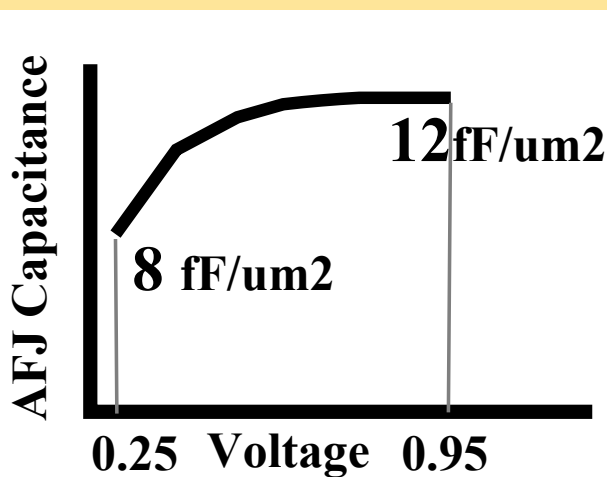
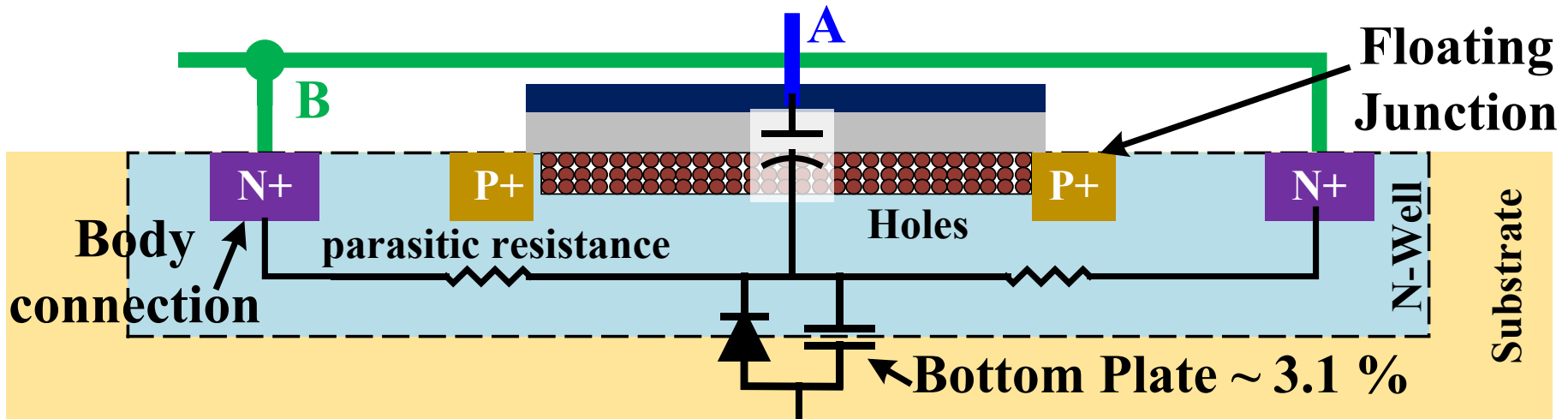
Passives I: Floating Junction HD Cap

- Wide output power range
 - Desired constant efficiency over output
 - Modular open loop helps



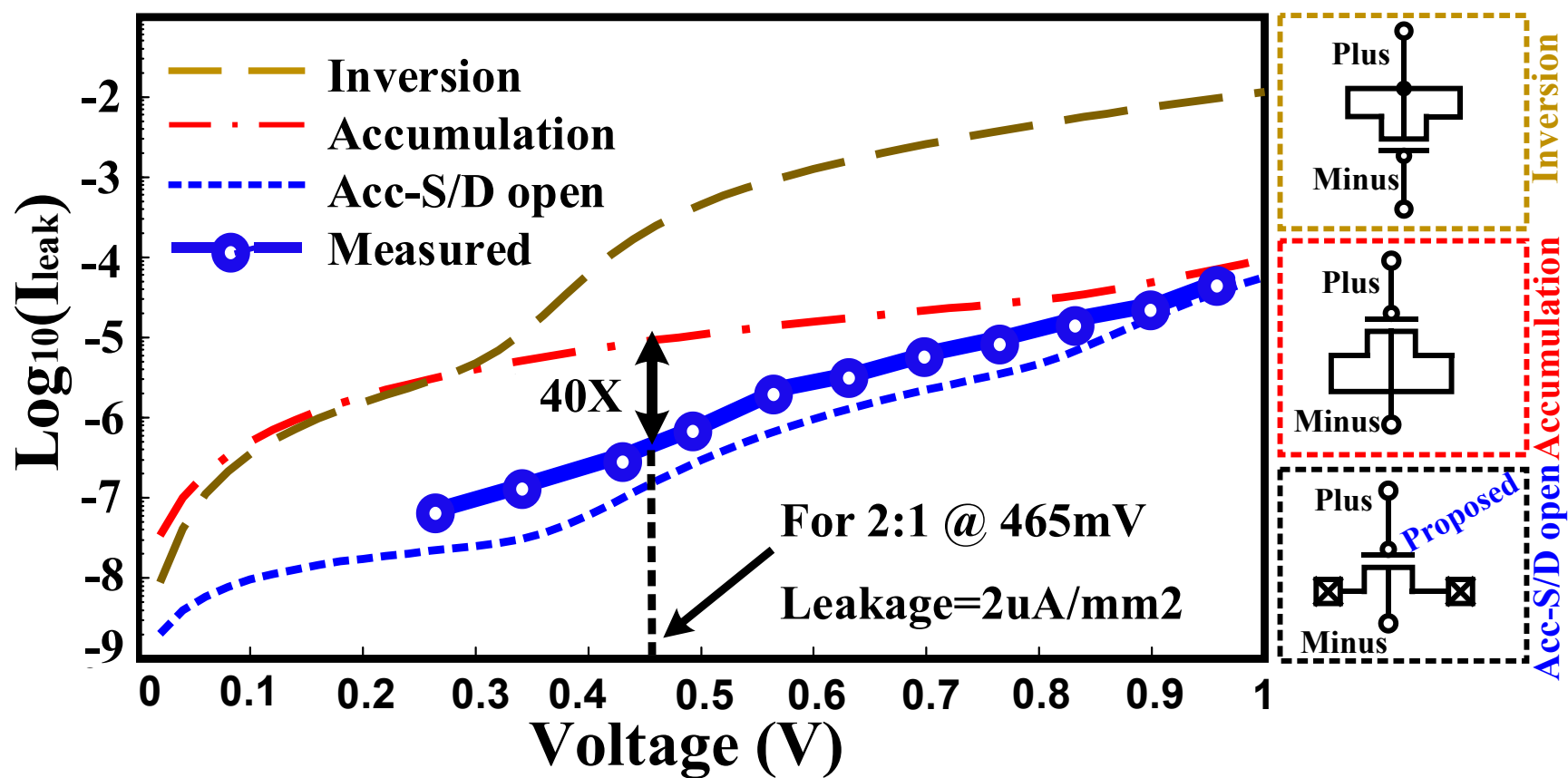
Passives II

- Cross section - Accumulation Floating Junction (AFJ)

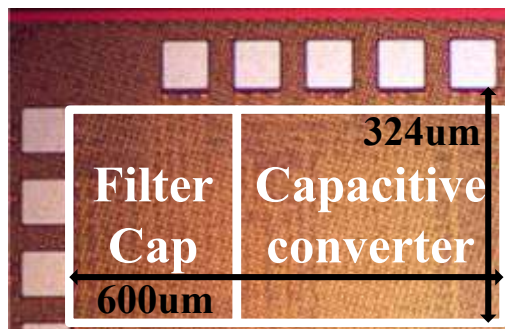


Passives III (Leakage Measurement)

- 40X improvement
- Floating source/drain



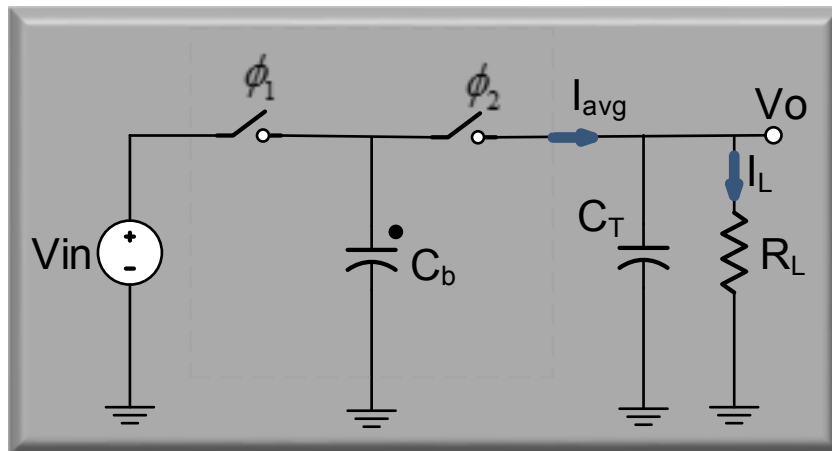
Unified Series Parallel Capacitive DC-DC Converter Framework



Ramesh Harjani, Saurabh Chaubey,
CICC 2014

1:1 Converter (IPG-OPG)

- Figure shows a 1: 1 capacitor converter
 - I.e., the maximum voltage at the output is V_{in} , $(V_o \leq V_{in})$
- Bucket capacitor, C_b , charged to V_{in} during input Φ_1
- C_b discharge to V_o during Φ_2
- The tank capacitor is much larger $C_T \gg C_b$
 - I.e., V_o can be assumed to be fairly constant



IPG-OPG Capacitive Converter

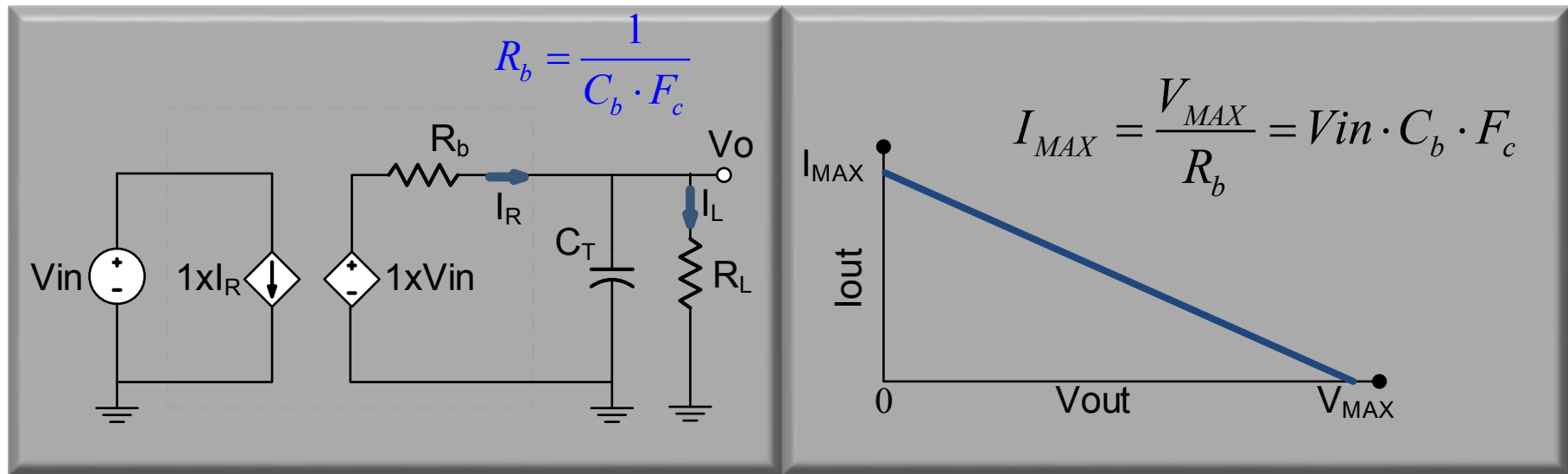
$$\Delta Q = (V_{in} - V_o) C_b \text{ per cycle}$$

$$I_{avg} = \Delta Q \cdot F_c = (V_{in} - V_o) C_b \cdot F_c = I_L$$

$$R_{avg} = \frac{\Delta V}{I_{avg}} = \frac{(V_{in} - V_o)}{(V_{in} - V_o) C_b \cdot F_c} = \frac{1}{C_b \cdot F_c}$$

Transformer Model for IPG-OPG

- Transformer model for 1:1 capacitive converter
- Load line for IPG-OPG converter
- Maximum current when V_o approaches zero
- When $V_o = V_{in} \rightarrow$ no charge transferred to output

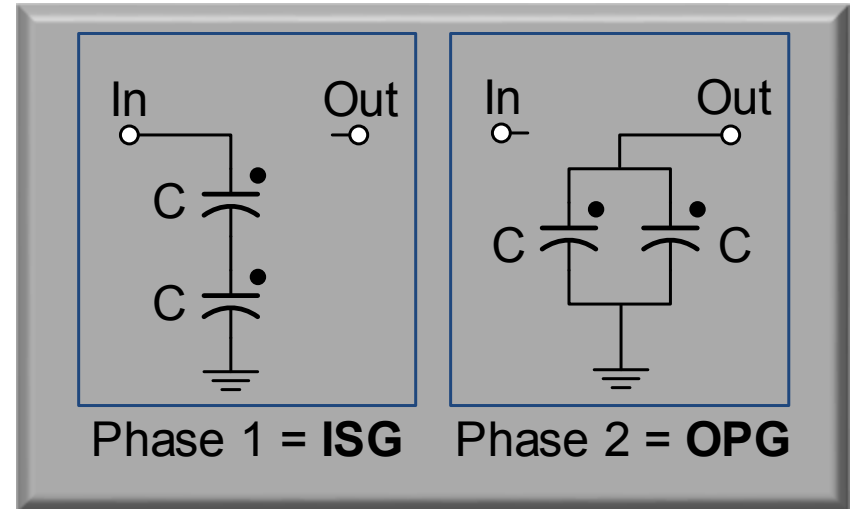


IPG-OPG Converter Transformer Model

IPG-OPG Load Line

Buck Converter #1 (ISG-OPG)(1 : 1/2)

- Φ_1 each capacitor charged to $V_i/2$
- Φ_2 both capacitors discharged to V_o



$$\Delta Q_1 = 0$$

$$\Delta Q_2 = 2 \left(\frac{V_i}{2} - V_o \right) C$$

$$I_o = \left(2 \left(\frac{V_i}{2} - V_o \right) C + 0 \right) F_c$$

$$R_o = \left(\frac{V_{max} - V_o}{I_o} \right) = \frac{1}{2 \cdot C \cdot F_c}$$

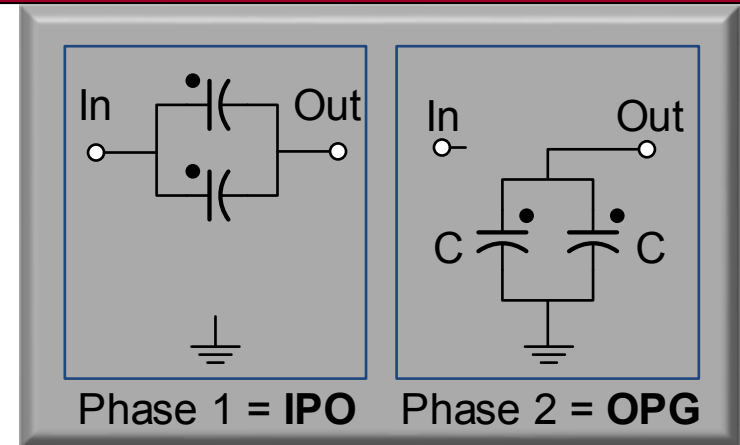
$$V_{max} = \frac{V_i}{2}$$

$$R_o = \frac{1}{N \cdot C \cdot F_c}$$

$$Area = N \cdot Area_c$$

Buck Converter #2 (IPO-OPG) (1 : 1/2)

- Φ_2 caps parallel to V_{out}
 - Charged to V_{out}
- Φ_1 caps in parallel between input and output
 - Caps charged to $V_{in}-V_o$
- Charge transferred to output during each phase
- Calculating V_{max}



$$\Delta Q_1 = [(V_i - V_o) - V_o] 2C$$

$$\Delta Q_2 = [(V_i - V_o) - V_o] 2C$$

$$I_o = (\Delta Q_1 + \Delta Q_2) F_c$$

$$= 2 \left(\frac{V_i}{2} - V_o \right) 4C \cdot F_c$$

$$R_o = \frac{1}{4N \cdot C \cdot F_c}$$

$$(V_{in} - V_o) = V_o \rightarrow V_{\max} = \frac{V_{in}}{2}$$

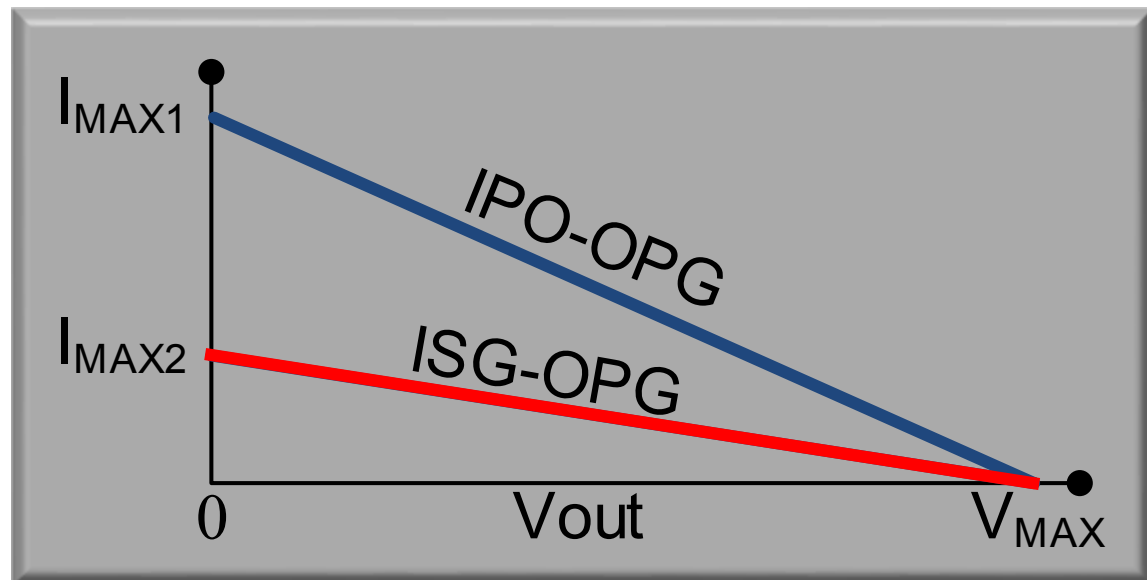
$$Area = N \cdot Area_c$$

Quick Summary: Topology Selection

- Same total capacitance used to compare designs
 - $N=2, C=1$
- Some topologies are just better than others
 - Lower $R_o \rightarrow$ can provide larger current
 - **IPO-OPG**: charges during $\Phi 1$ and $\Phi 2 \rightarrow$ lower ripple

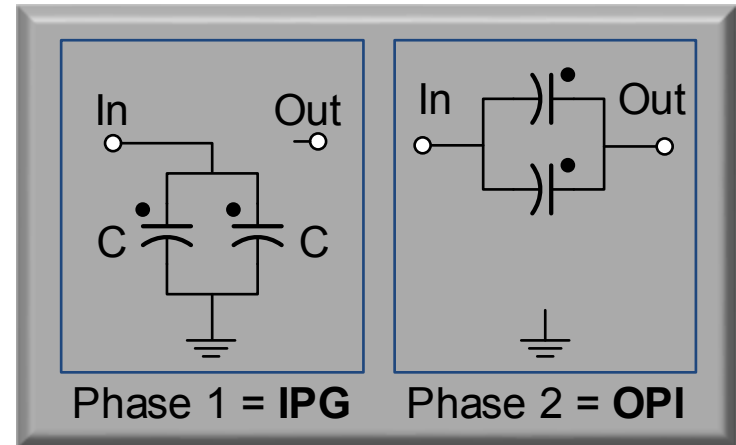
$$R_o = \frac{1}{4N \cdot C \cdot F_c}$$

$$R_o = \frac{1}{N \cdot C \cdot F_c}$$



Boost Converter: (IPG-OPI) (1 : 2)

- Φ_1 parallel capacitors connected to V_i
- Φ_2 parallel capacitors between V_o and V_i
 - Note phase of capacitors
- Calculating V_{max}



$$\Delta Q_1 = 0$$

$$\Delta Q_2 = [(V_i - V_o) + V_i] 2C$$

$$I_o = [0 + (2V_i - V_o) 2C] F_c$$

$$R_o = \frac{1}{N \cdot C \cdot F_c}$$

$$Area = N \cdot Area_c$$

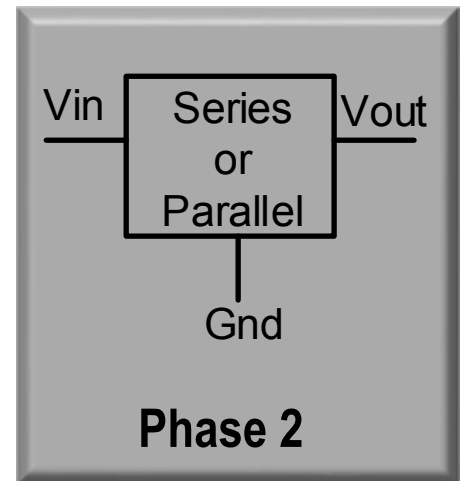
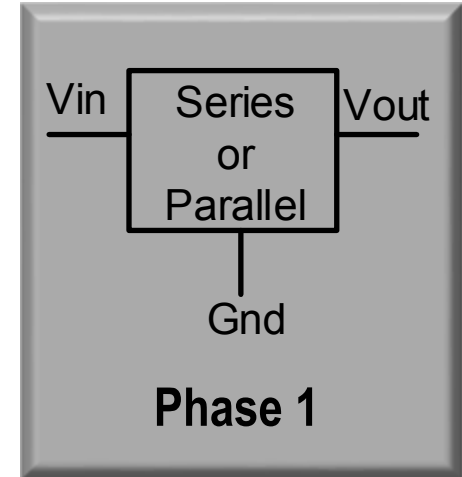
Design Rules

■ Motivation

- Currently, ad hoc single point solutions
- No generalized set of topologies & equations

■ Heuristic rules

- Ripple voltage is small
- Only three terminal designs
- All bucket caps same size
- All bucket caps move as one group
- The bucket caps are in series or parallel
- A cycle is composed of two phases
- All three terminals used during each cycle

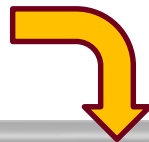


Nomenclature

■ Phase notation we will use

Position	Code	Description
1st	I, G, O	1st connection (Input, Output, Gnd)
2nd	P, S	Series or Parallel
3rd	I, G, O	2nd connection (Input, Output, Gnd)

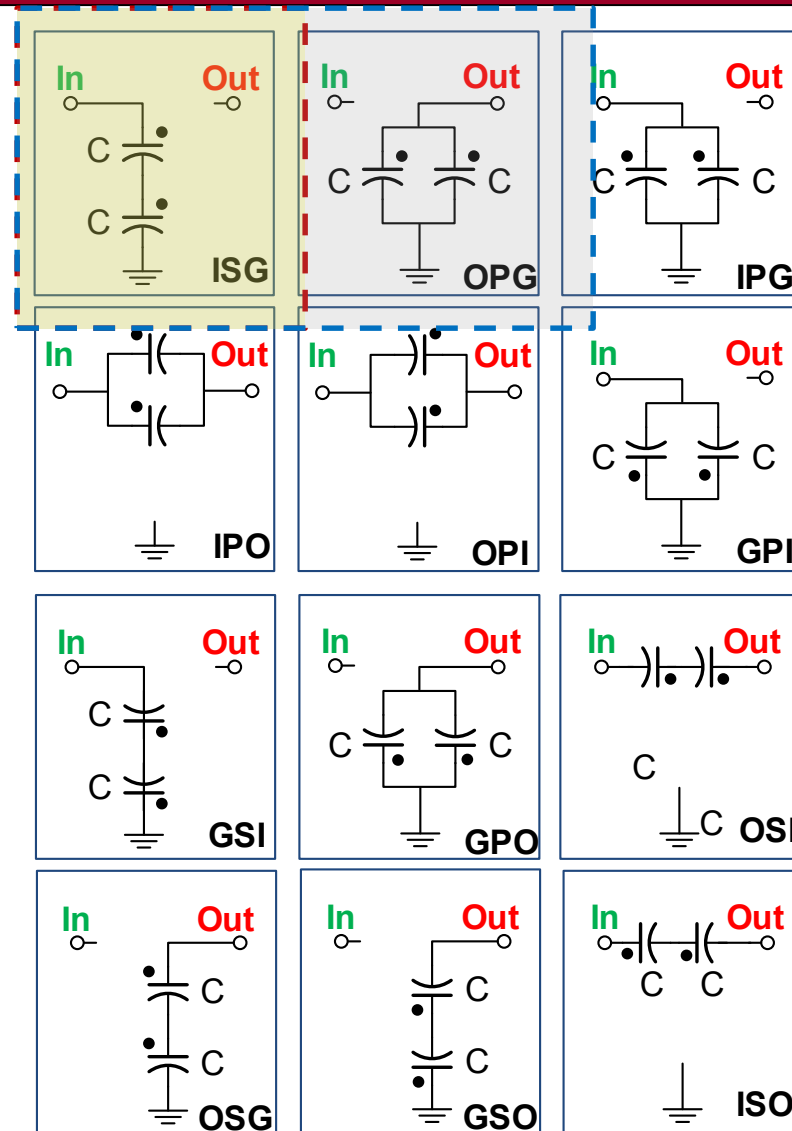
$$3 \times 2 \times 2 = 12 \text{ phases}$$



IPG	IPO	GPI	GPO	OPI	OPG
ISG	ISO	GSI	GSO	OSI	OSG

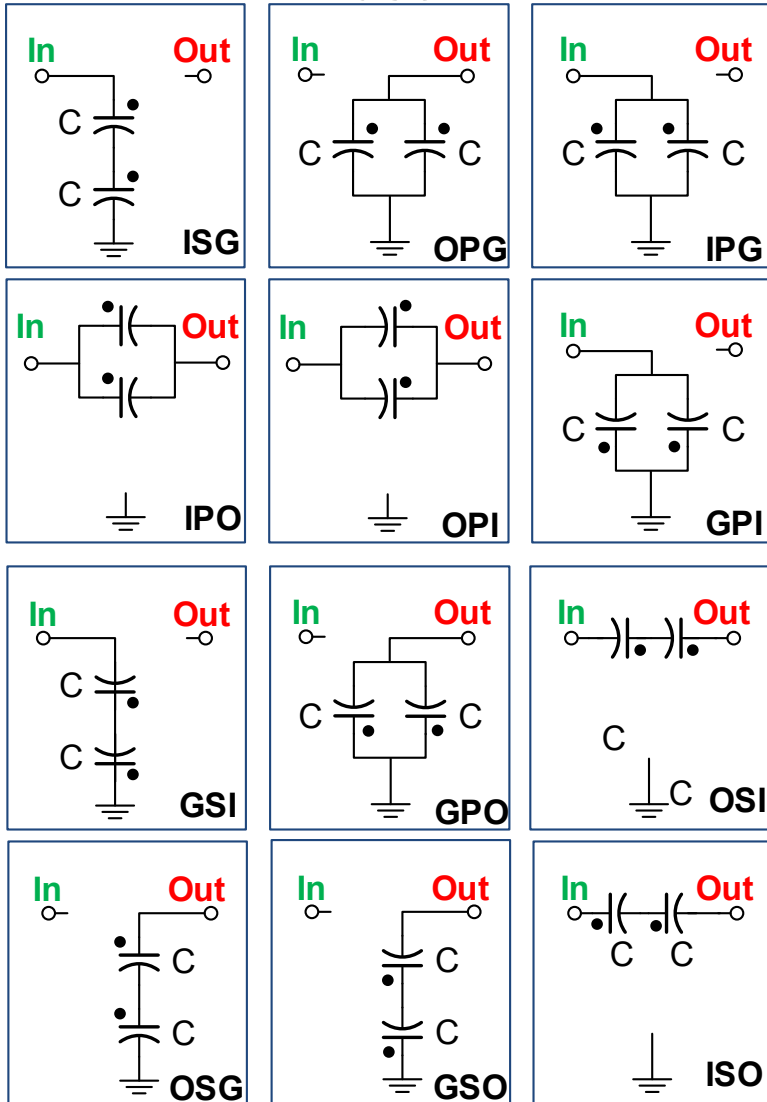
12 Distinct Configurations

Configuration Topology



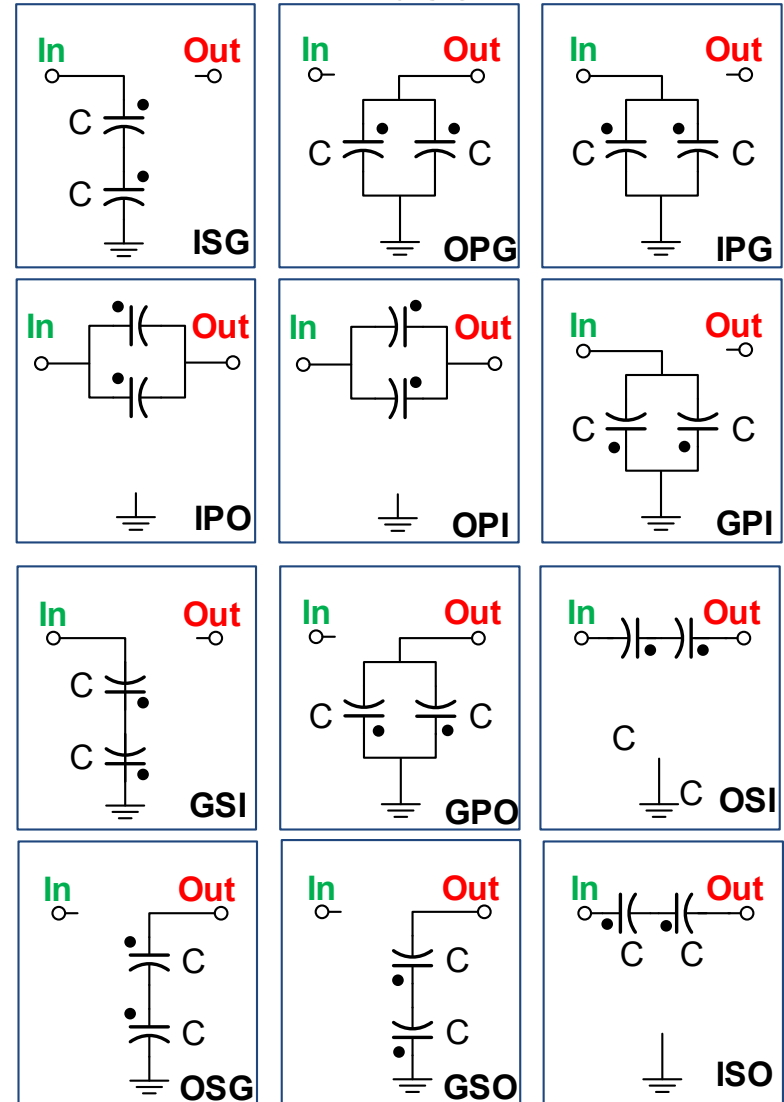
Configuration to Topology

Phase 1



X

Phase 2



Enumeration

- 12 configurations for 1st phase
- For two phases (12 x 11=132) combinations
- Apply the heuristic rules: reduces to 96
- More heuristic rules
 - Same 2 phases but different order: ISG-IPO ; IPO-ISG
 - Series or parallel in both phases: ISG-ISO = IPG-IPO
 - Flipping 1st and 3rd letter (IPG-IPO=GPI-OPI)

18 structurally  **unique topologies**

IPG-IPO IPG-GPO IPG-OPI IPG-OPG IPG-ISO IPG-GSO
IPO-GPO IPO-OPG IPO-ISG IPO-GSI IPO-GSO GPO-ISG
GPO-OSI IPG-OSI IPO-OSG IPG-OSG GPO-ISO GPO-GSI

Derivation of Performance

■ Generic performance equations

$$V_{max} = K \times V_{in}$$

—————→ No load voltage

$$I_{out} = (F_{sw} \cdot C) \times f(V_{in}, V_{out}, N)$$

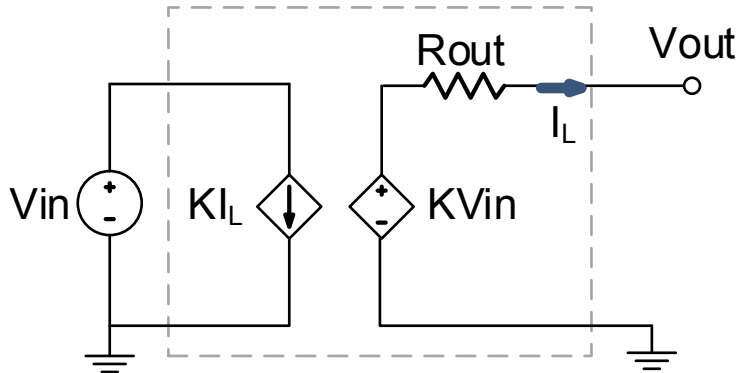
—————→ Output current

$$I_{ratio} = \frac{I_{out}}{I_{in}} = K$$

—————→ Conversion ratio

$$P_{eff} = \frac{P_{out}}{P_{in}} = \frac{V_{out}}{V_{max}}$$

—————→ Power efficiency



Performance Equations: Final Set

MODE	K	Rout	Nmin
IPG-OSI	N+1	$\frac{N}{fC}$	2
IPG-OPI	2	$\frac{1}{fCN}$	1
ISG-OPI	$\frac{N+1}{N}$	$\frac{1}{fCN}$	2

Boost performance equations

MODE	K	Rout	Nmin
IPG-OPG	1	$\frac{1}{fCN}$	2
IPO-OSG	$\frac{N}{N+1}$	$\frac{N}{fC(N+1)^2}$	1
IPO-OPG	$\frac{1}{2}$	$\frac{1}{4fCN}$	2
ISO-OPG	$\frac{1}{N+1}$	$\frac{N}{fC(N+1)^2}$	2

MODE	K	Rout	Nmin
ISG-GPO	$-\frac{1}{N}$	$\frac{1}{fCN}$	2
IPG-GPO	-1	$\frac{N}{fCN}$	1
IPG-GSO	-N	$\frac{N}{fC}$	2

Negative performance equations

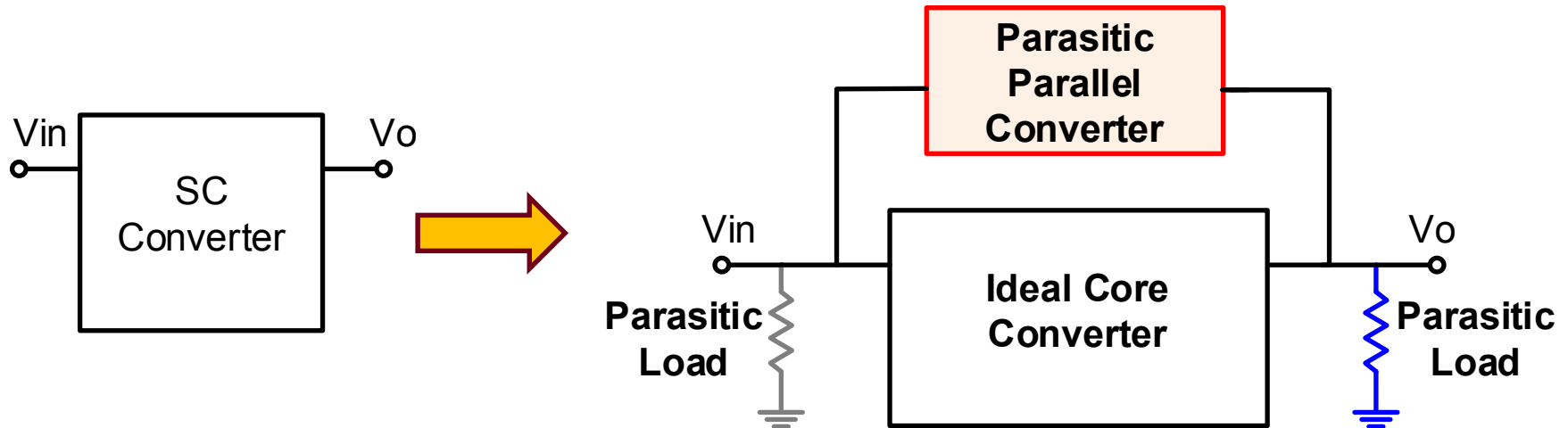
IPG-OSG	OPI-OSG	IPO-ISG	ISG-OPG
ISO-GPO	IPG-ISO	IPG-IPO	OPG-OPI

Non-optimum cases

Only 10 Optimum Topologies

Modeling Capacitor Parasitics

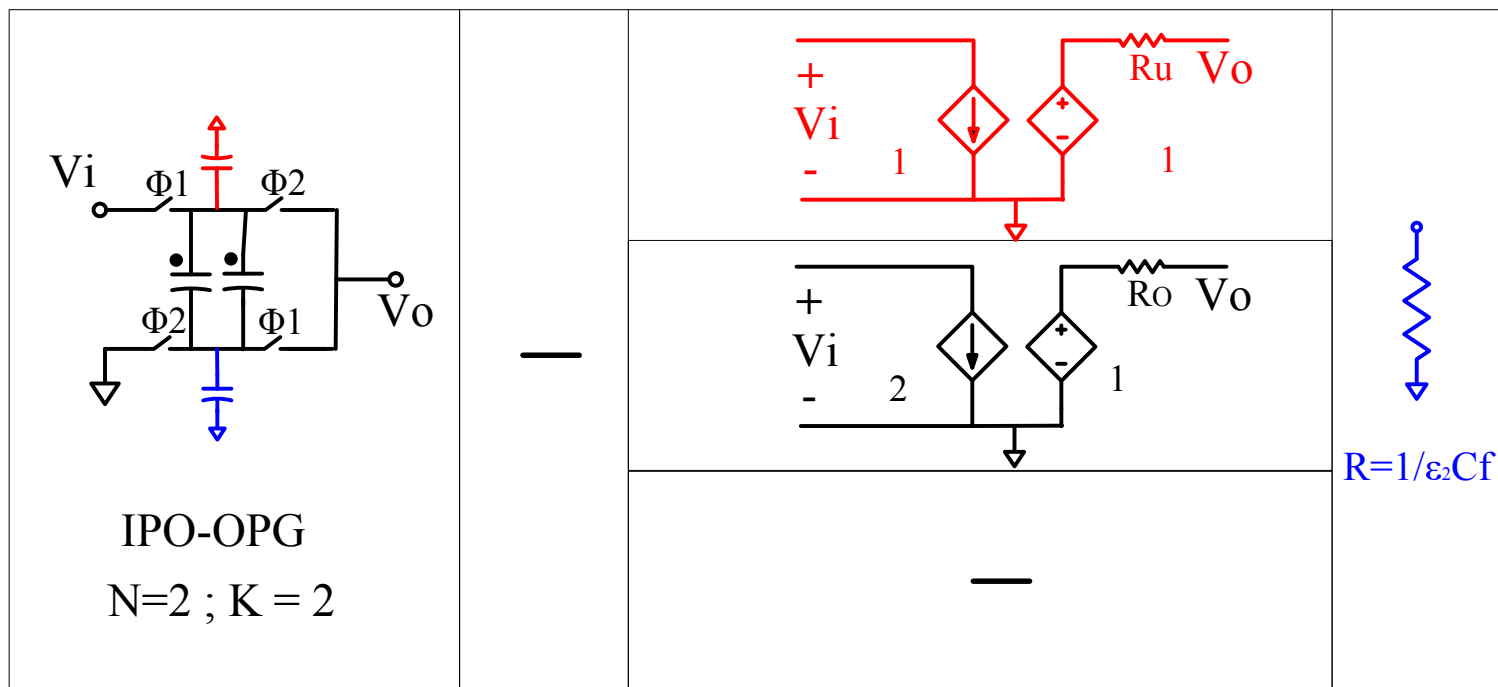
- Top / bottom parasitics modeled as conduction loss
- Capacitor parasitics
 - Parasitic **input** load
 - Parasitic **output** load
 - Parasitic **parallel** converter



Effect Of Parasitics

■ Example: IPO-OPG

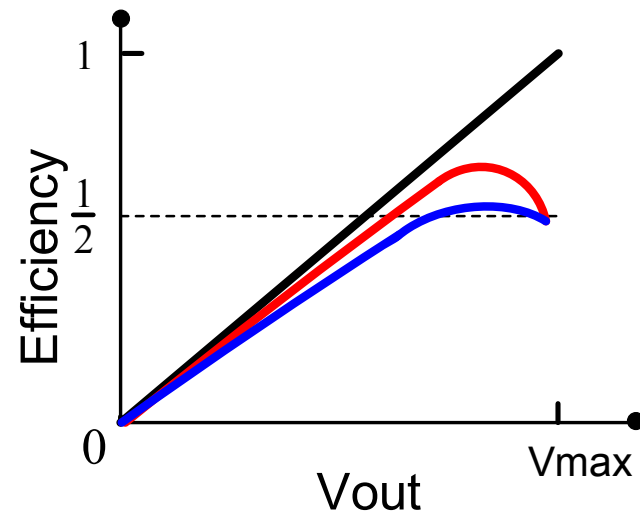
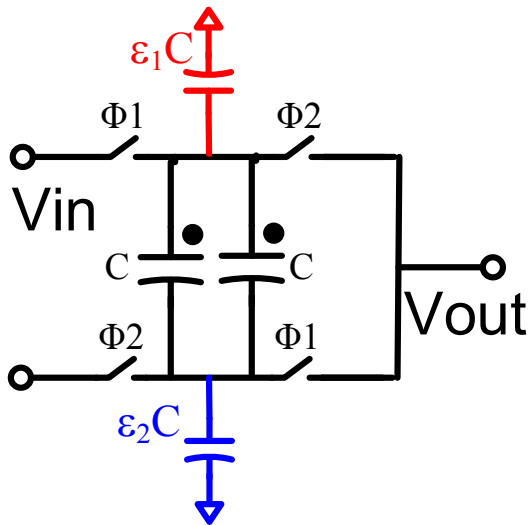
- Top plate acts as 1:1 parallel converter
 - Takes charge from V_{in} in Φ_1 dumps on load in Φ_2
- Bottom plate acts as a passive load
 - Takes charge from V_{out} in Φ_1 and dumps to ground Φ_2



Parasitic Modeling

- Bottom plate further reduces efficiency

$$\eta = \frac{\left[4 \left(\frac{V_i}{2} - V_o \right) C_b f + \epsilon_1 (V_i - V_o) C_b f - \epsilon_2 V_o C_b f \right]}{\left[2 \left(\frac{V_i}{2} - V_o \right) C_b f + \epsilon_1 (V_i - V_o) C_b f \right]} \left(\frac{V_o}{V_i} \right)$$



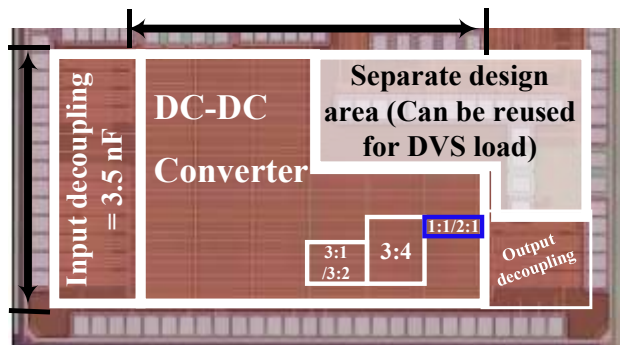
Parasitics

- All 10 topologies
- For each topology
 - Primary converter
 - Parasitic input load
 - Parasitic output load
 - Parasitic converter

<p>IPG-GPO N=2 ; K = -1</p>	<p>$R=1/\epsilon C_f$</p> <p>$R=1/\epsilon C_f$</p>	<p>OPI-IPG N=2 ; K = 1/2</p>	<p>$R=1/\epsilon C_f$</p> <p>$R=1/\epsilon C_f$</p>
<p>IPG-OPG N=2 ; K = 1</p>	<p>—</p> <p>—</p>	<p>IPG-OSI N=2 ; K = 1/3</p>	<p>$R=1/\epsilon C_f$</p> <p>—</p>
<p>IPG-GSO N=2 ; K = -1/2</p>	<p>$R=1/\epsilon C_f$</p> <p>$R=2/\epsilon C_f$</p> <p>$R=1/\epsilon C_f$</p>	<p>GPO-OSI N=2 ; K = 3</p>	<p>—</p> <p>$R=1/\epsilon C_f$</p>
<p>GPO-ISG N=2 ; K = -2</p>	<p>$R=1/\epsilon C_f$</p> <p>$R=1/\epsilon C_f$</p>	<p>IPO-GSI N=2 ; K = 2/3</p>	<p>$R=1/\epsilon C_f$</p> <p>$R=2/\epsilon C_f$</p>
<p>IPO-OPG N=2 ; K = 2</p>	<p>—</p> <p>$R=1/\epsilon C_f$</p>	<p>IPO-OSG N=2 ; K = 3/2</p>	<p>—</p> <p>$R=1/\epsilon C_f$</p> <p>$R=2/\epsilon C_f$</p>



Software Defined 3000X Output Current Range SC DC-DC Converter

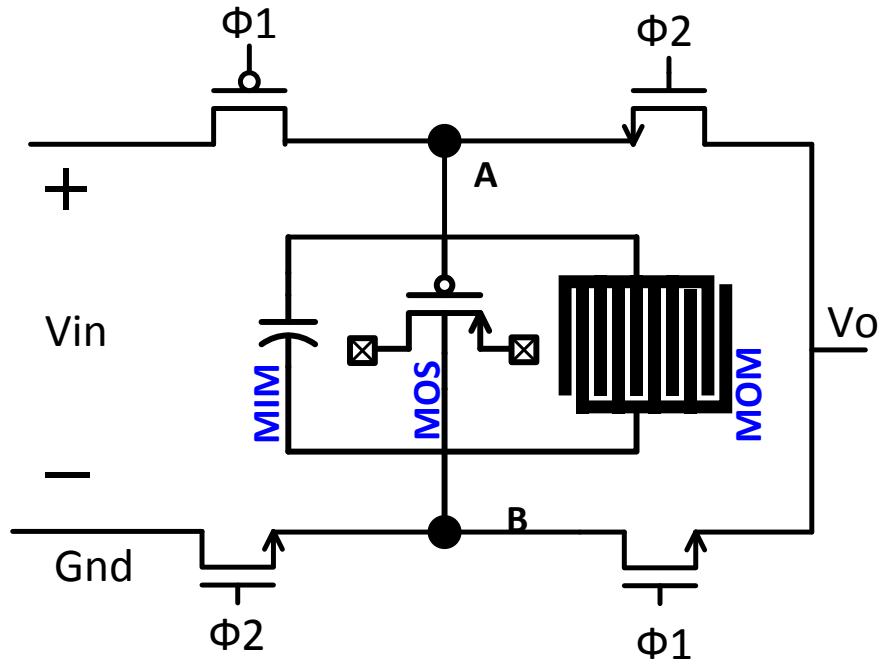
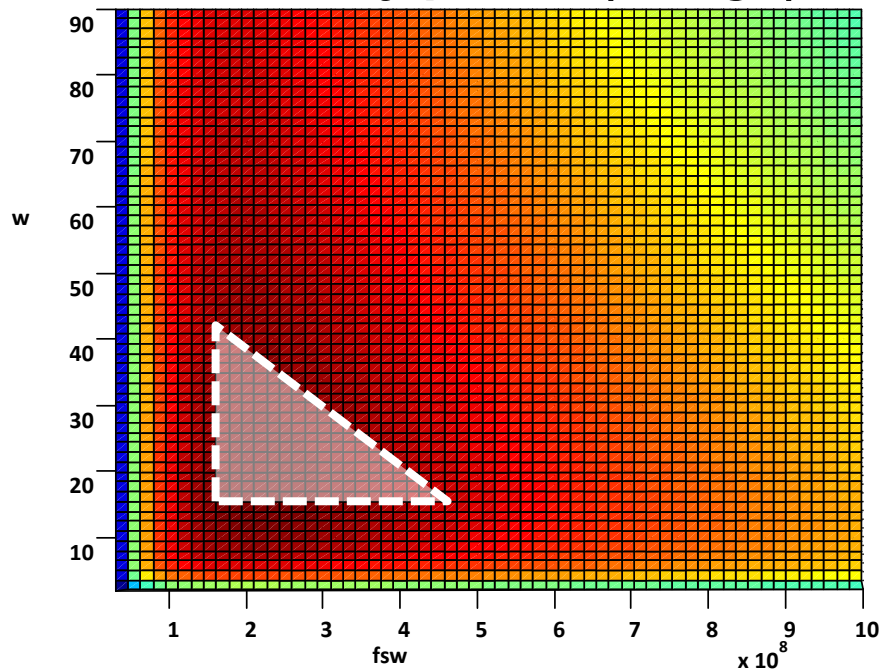


Process: TSMC 65 GP
Saurabh Chaubey
CICC 2017

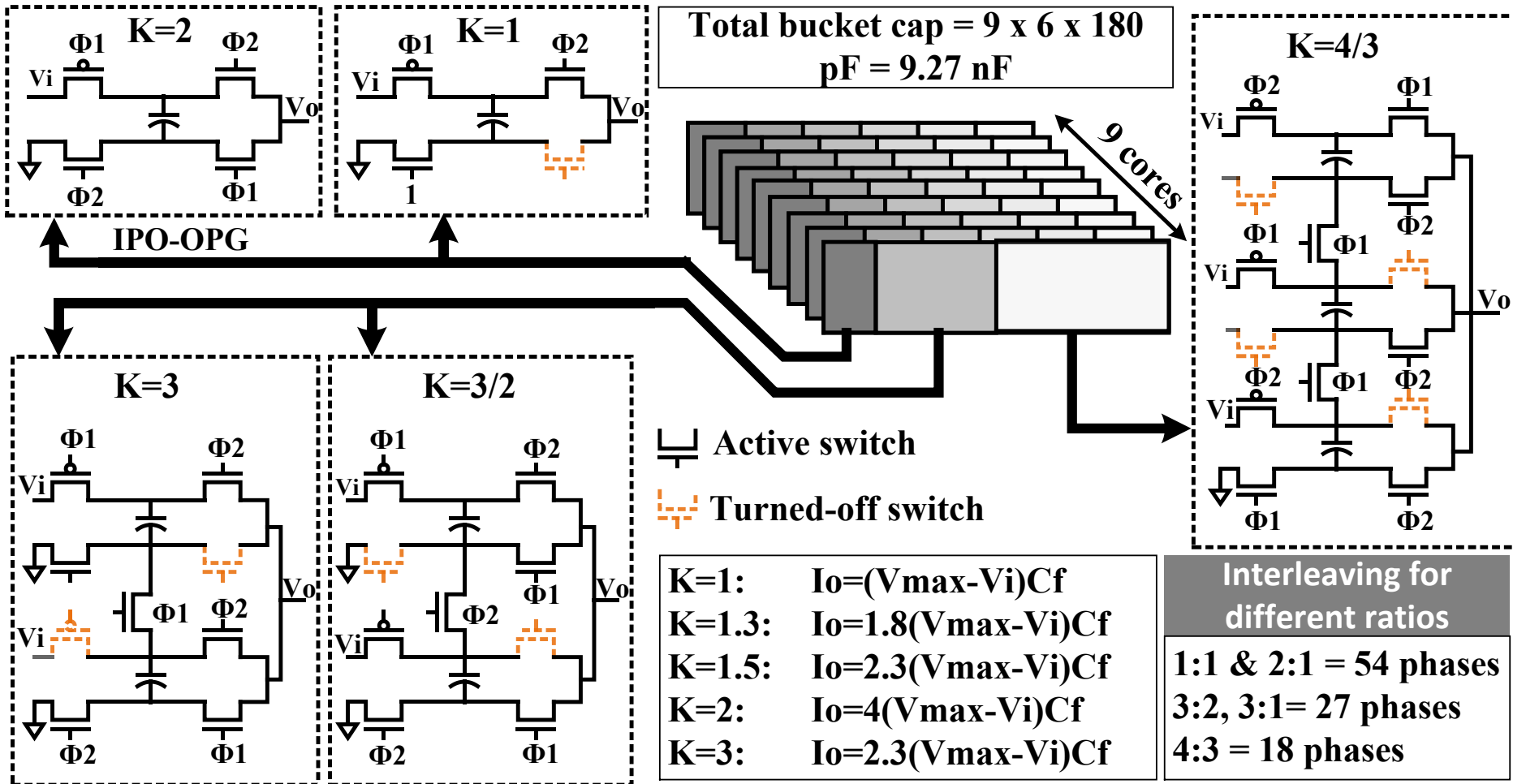
Single DC-DC Conversion Module

- Converter consists of standard cells
 - Each cell \rightarrow 2:1 converter (IPO-OPG)
 - 2:1 \rightarrow 1 IPO-OPG , 3:1 \rightarrow 2 IPO-OPG and so on
 - Passives \rightarrow custom high density cap \rightarrow **180 pF**

Efficiency profile (design)

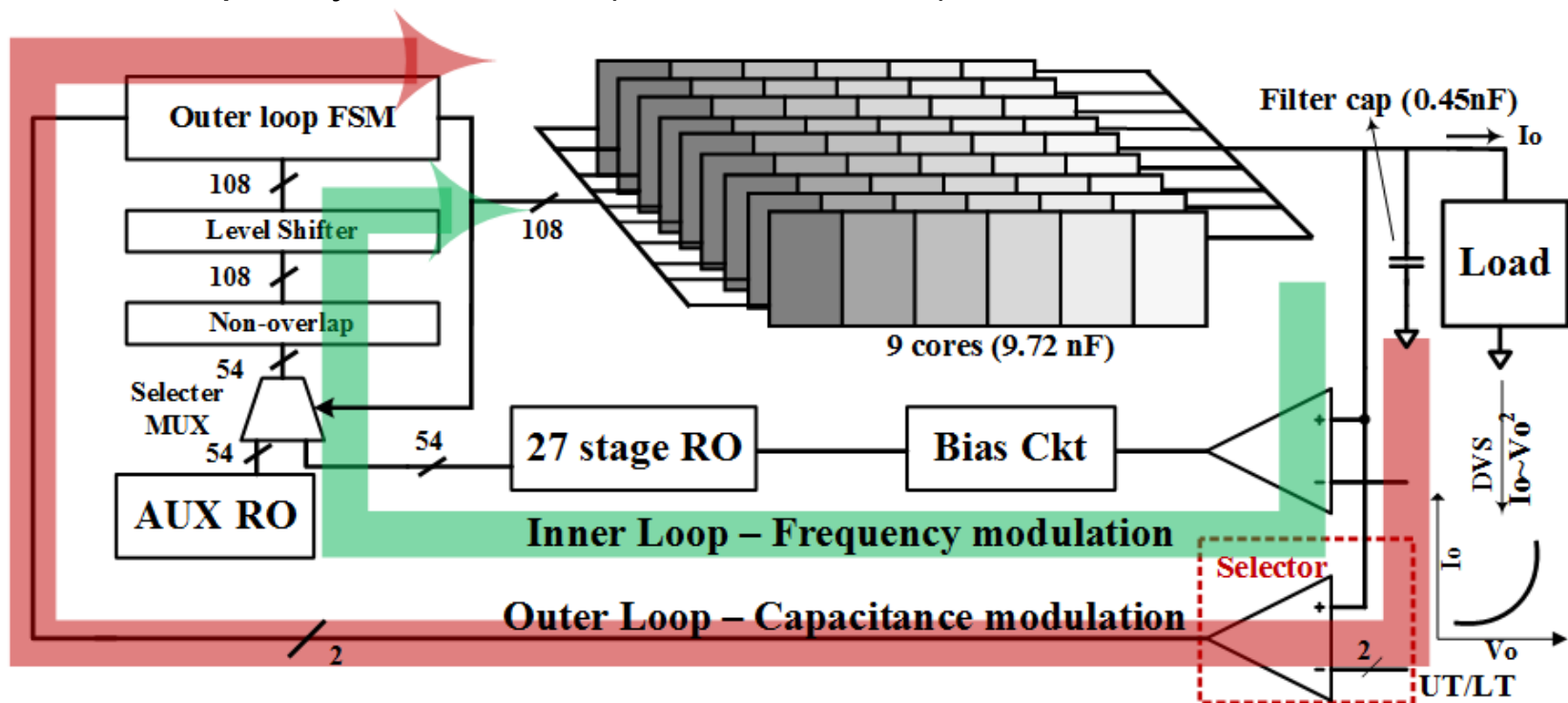


DC-DC Converter - Open Loop

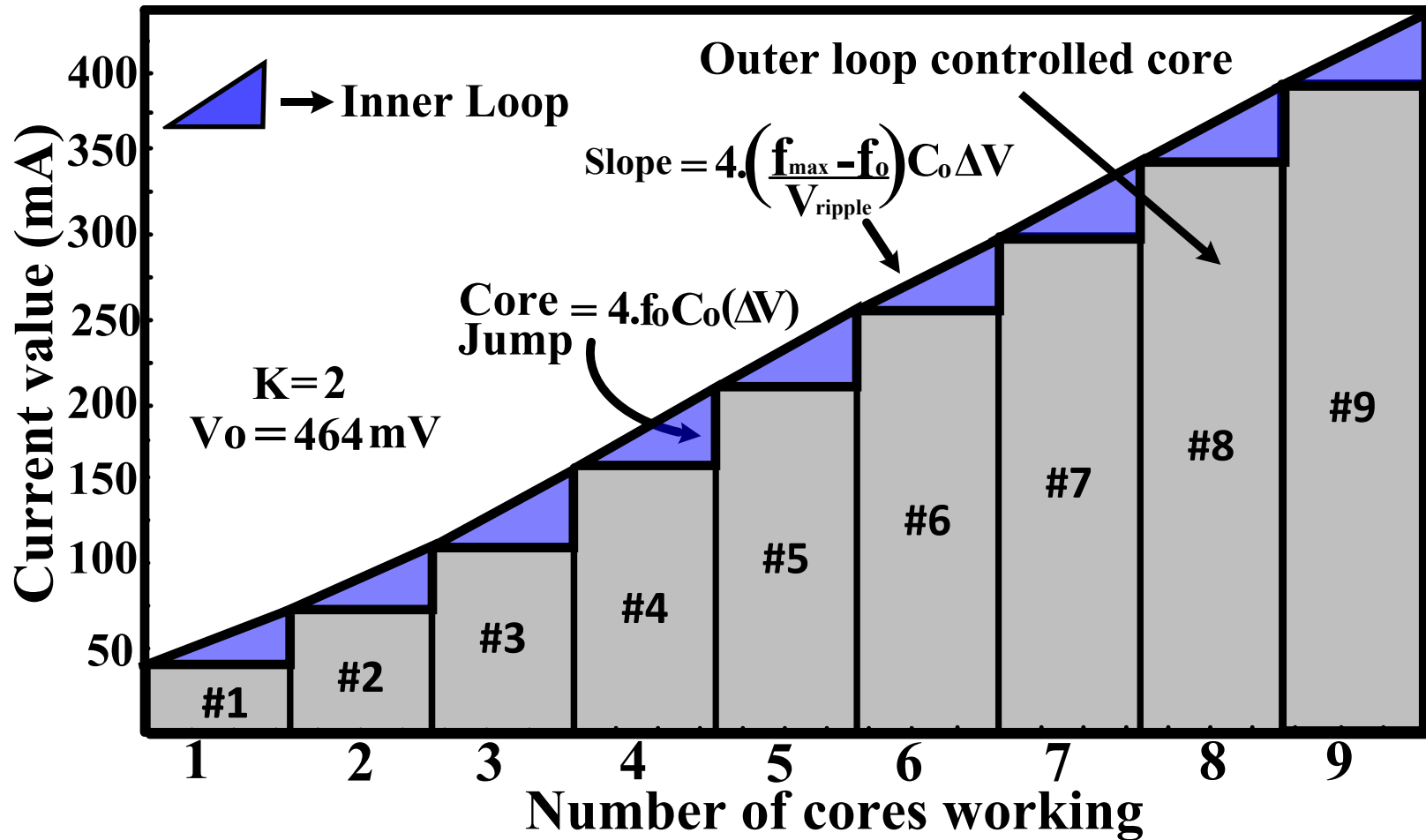


Architecture

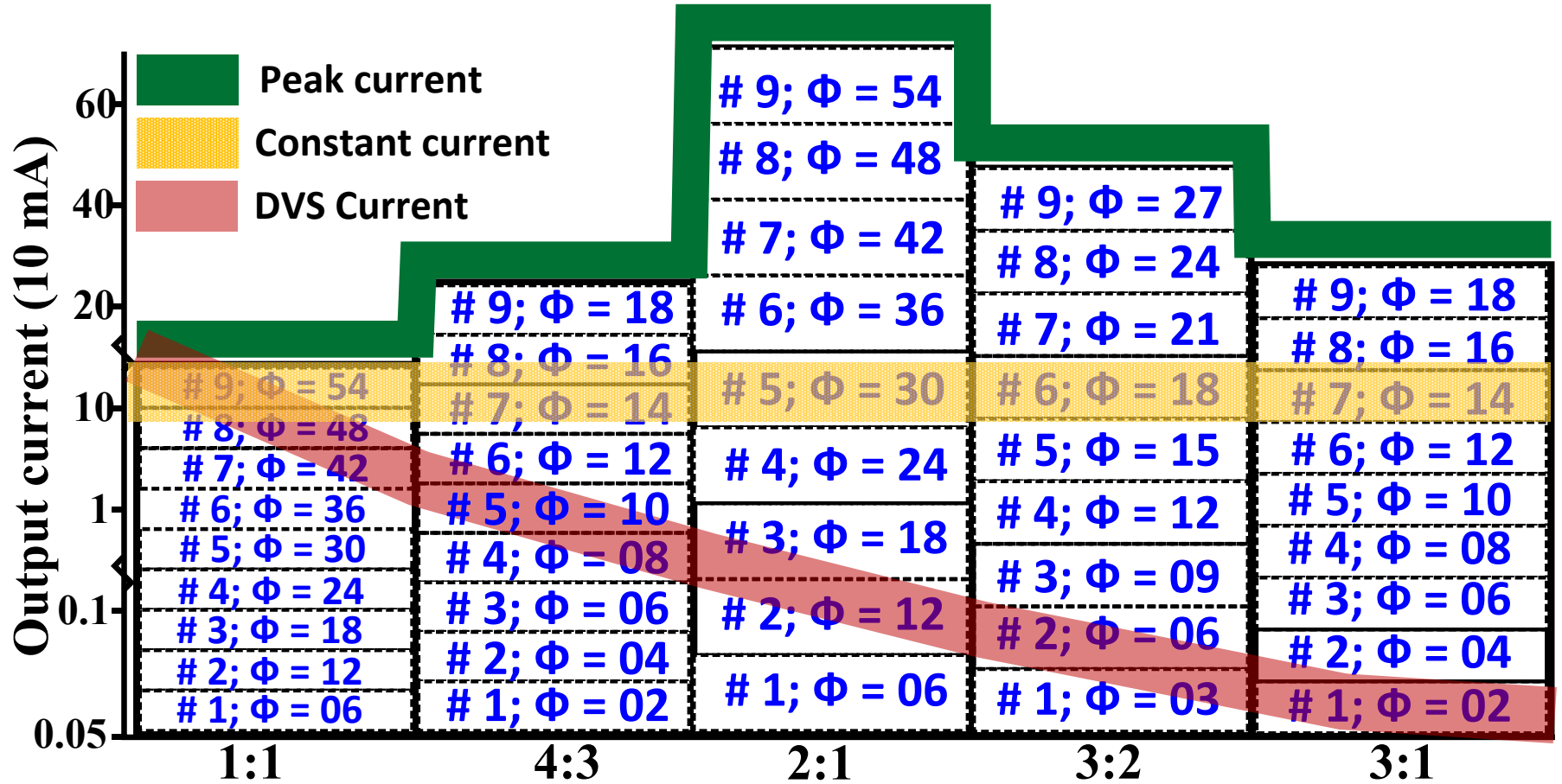
- Modular –digital standard cell based design
 - IPO-OPG cell is standard cell (180pF)
 - 6 cells → 1 core (1.08 nF)
- Dual loop modulation
 - Capacitive modulation (Nine levels) - Outer
 - Frequency modulation (RO based VCO) -Inner



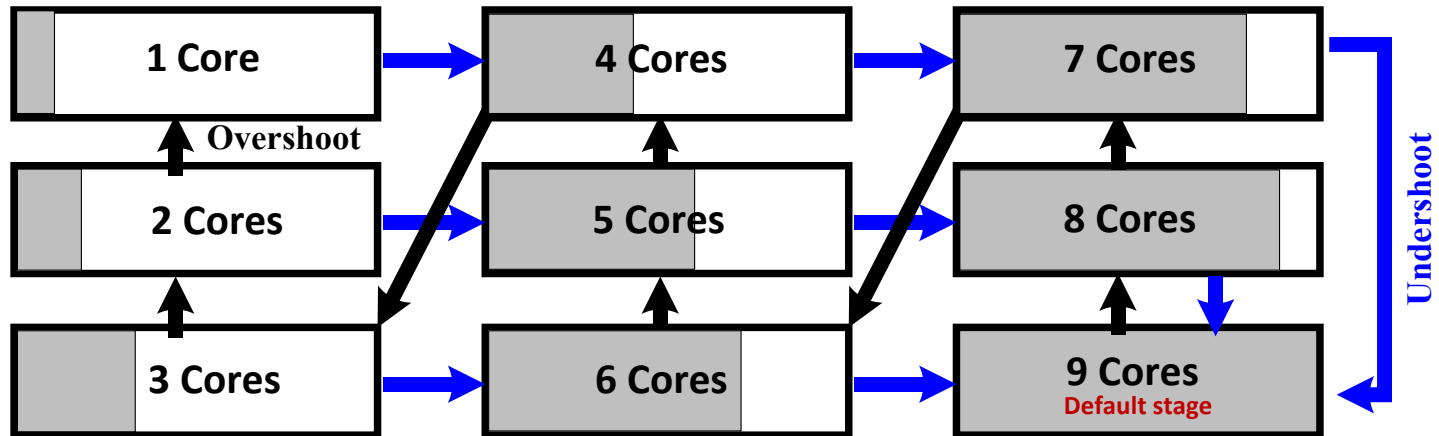
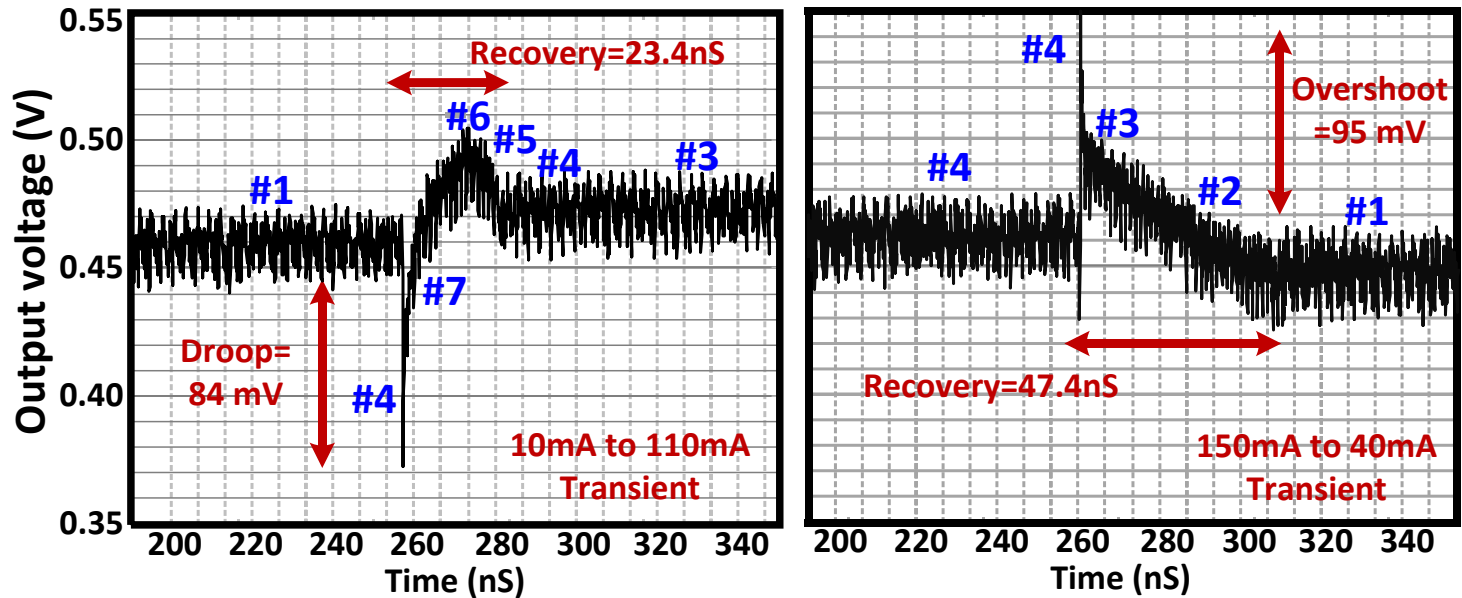
Outer Control Loop



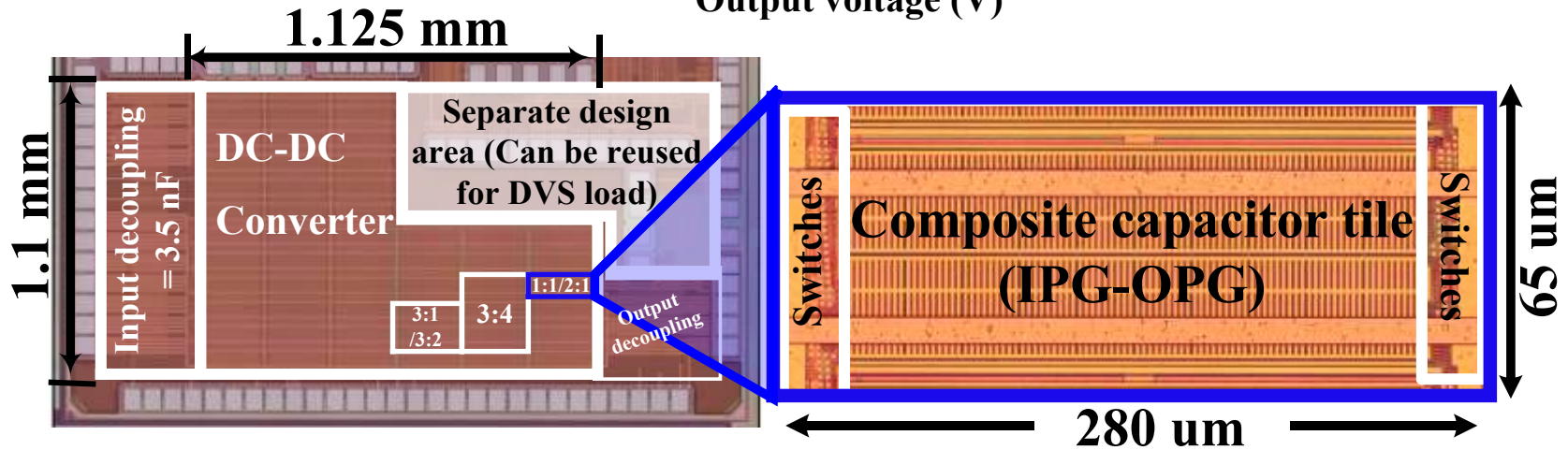
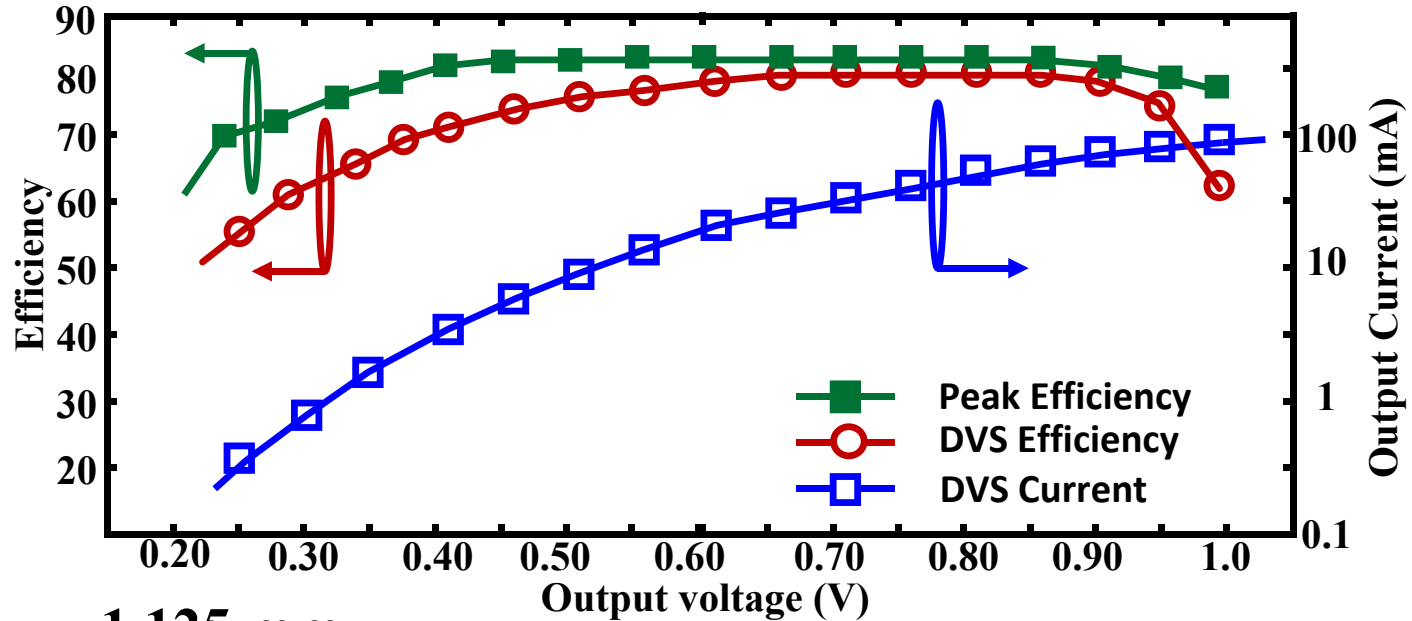
Overall Converter Dynamics



Measurement Results I

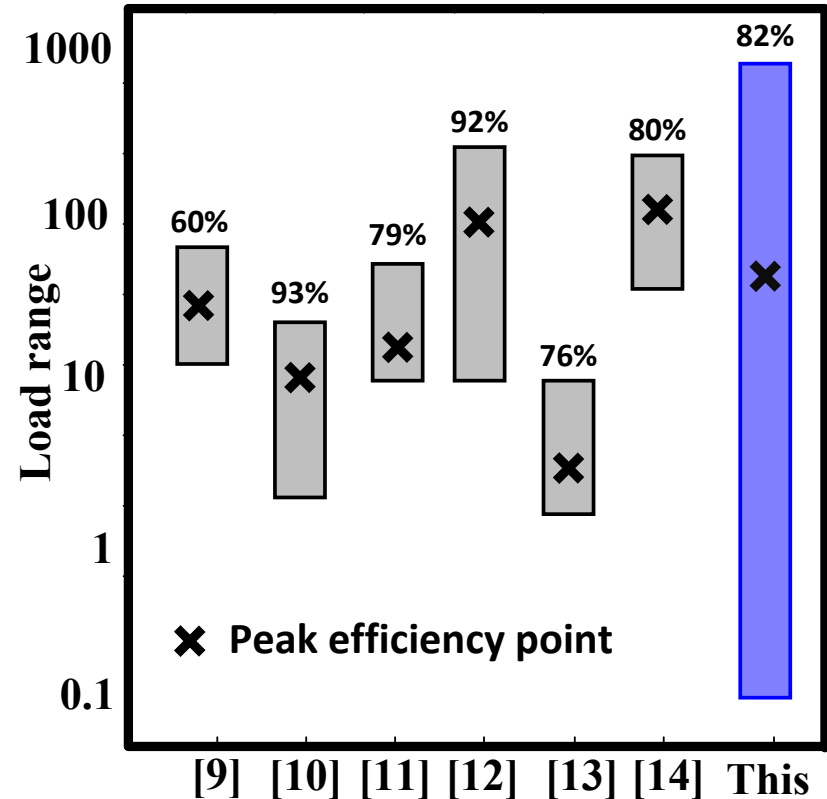
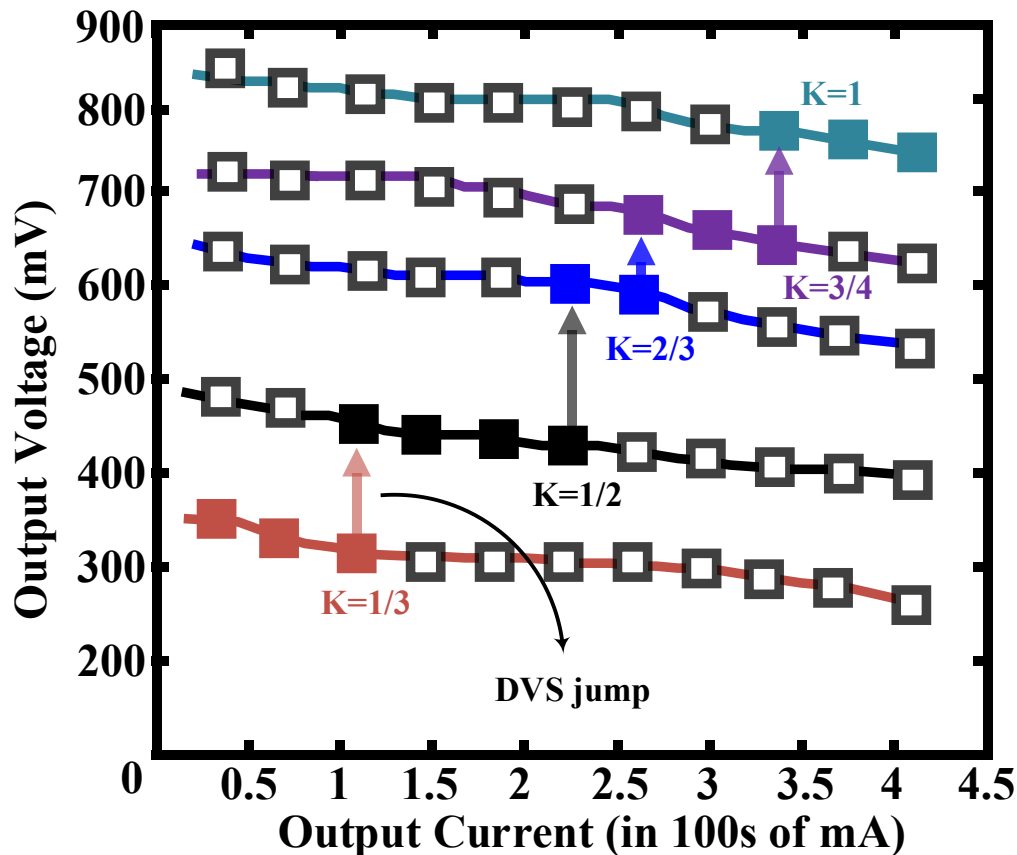


Combined Efficiency

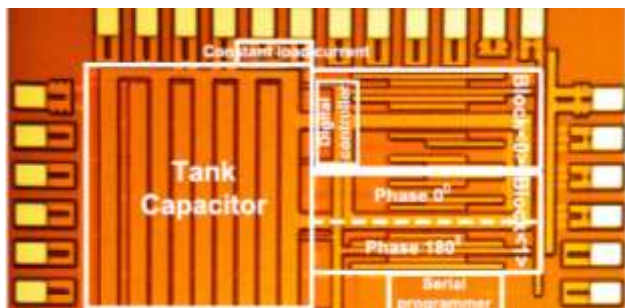


Comparison

- Widest output current range support
- Supports DVS



Fully Integrated Capacitive Converter with All Digital Ripple Mitigation



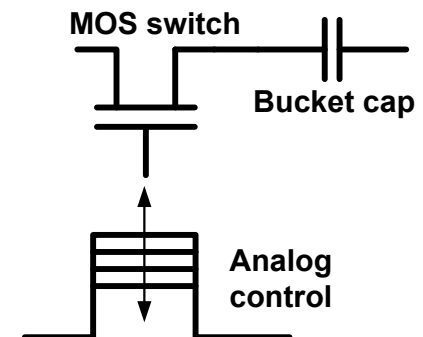
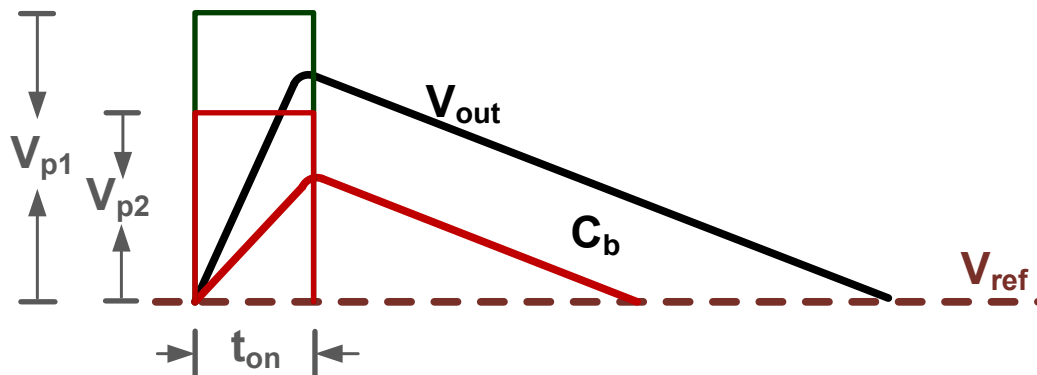
Process: IBM 130nm CMOS
Sudhir Kudva
IEEE CICC 2012, JSSC 2013

Ripple Control Techniques(I)

- Overshoot above nominal voltage
 - Results in wasteful power
- Ripple ↓ overall system efficiency ↑
- Conventional techniques
 - Increase switching frequency
 - Increase the interleaved stages
- Losses ↑ or area ↑ or need high frequency component
- Bucket capacitors designed for maximum load current
- Regulate the amount of charge transferred

Ripple Control Techniques (II)

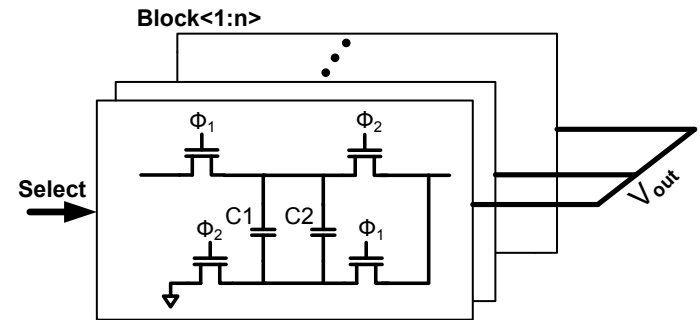
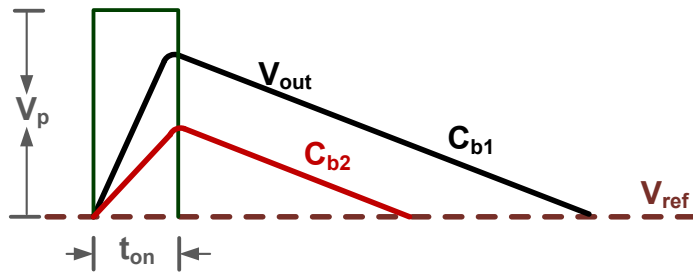
- Regulate the charge dumped into decap
- Unconventional ways to control charge transfer
- Three possible methods
- Switch resistance (method #1)
 - Gate voltage to vary resistance
 - Requires analog components



Ripple Control Techniques (III)

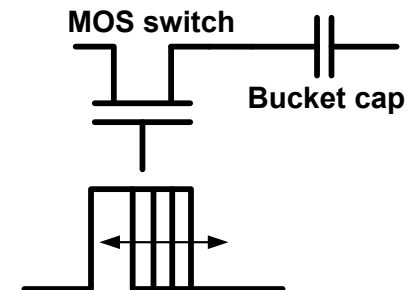
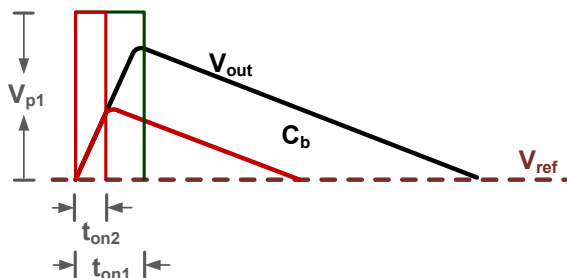
Capacitance modulation (method #2)

- Vary bucket cap size
- **Hard to attain fine resolution**



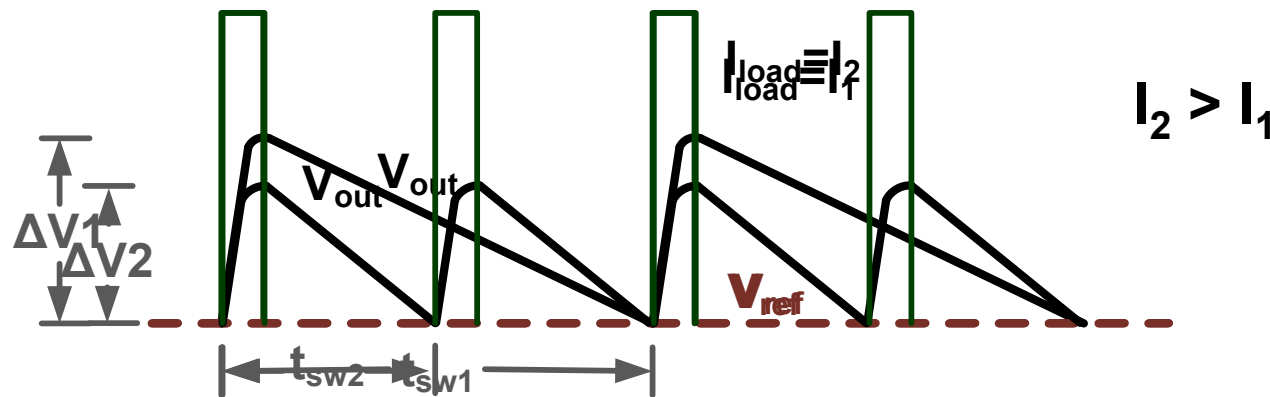
Pulse width modulation (method #3)

- Vary time of charge/discharge
- **Limited range of control**



Cap + Pulse Width Modulation (I)

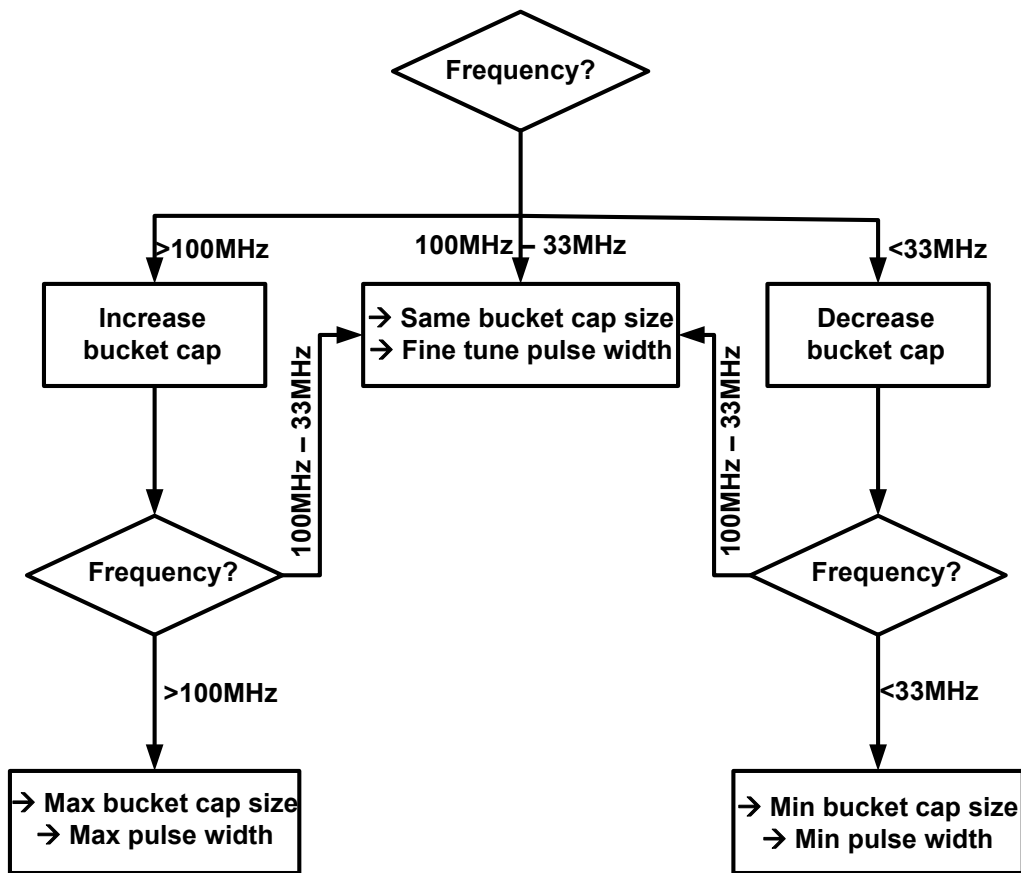
- Both cap + pulse width modulation digital in nature
 - → No analog components
- Easily scalable with technology
- Primary loop for regulation
 - Changes switching frequency



- Freq used as an indirect measure of ripple

Cap + Pulse Width Modulation (II)

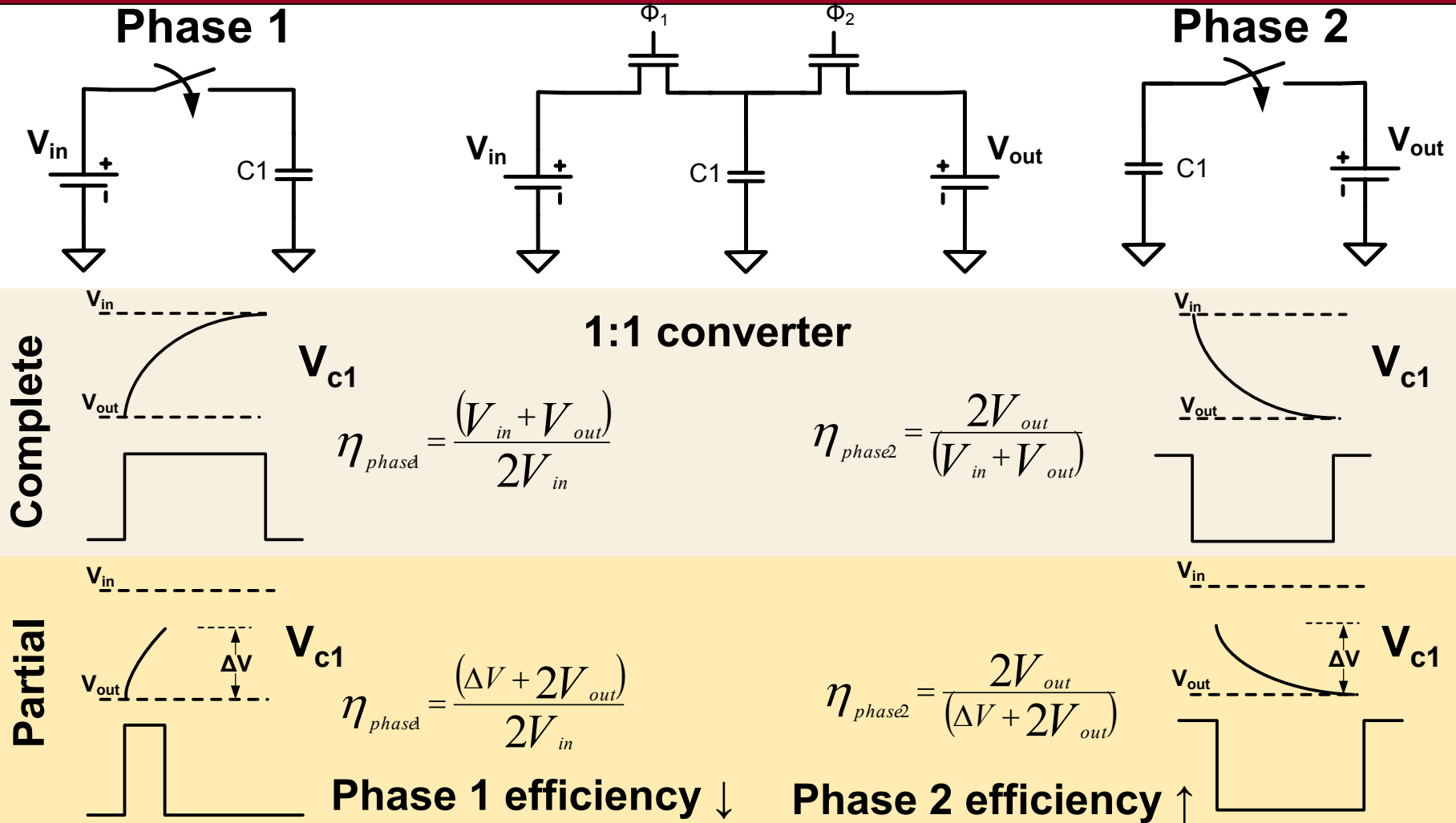
- Two step control
 - Course control → capacitance modulation
 - Fine control → pulse width modulation



All digital detection mechanism

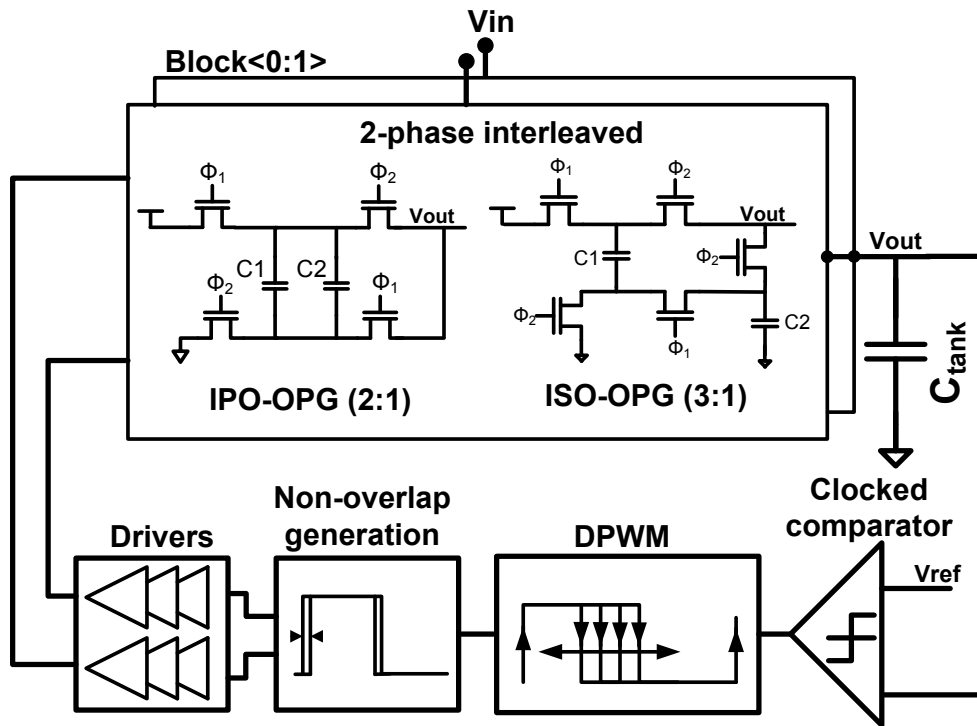
Easily scalable with technology

Partial Charge/Discharge → Efficiency



Total efficiency ($\eta_{phase1} \times \eta_{phase2} = \frac{V_{out}}{V_{in}}$) same

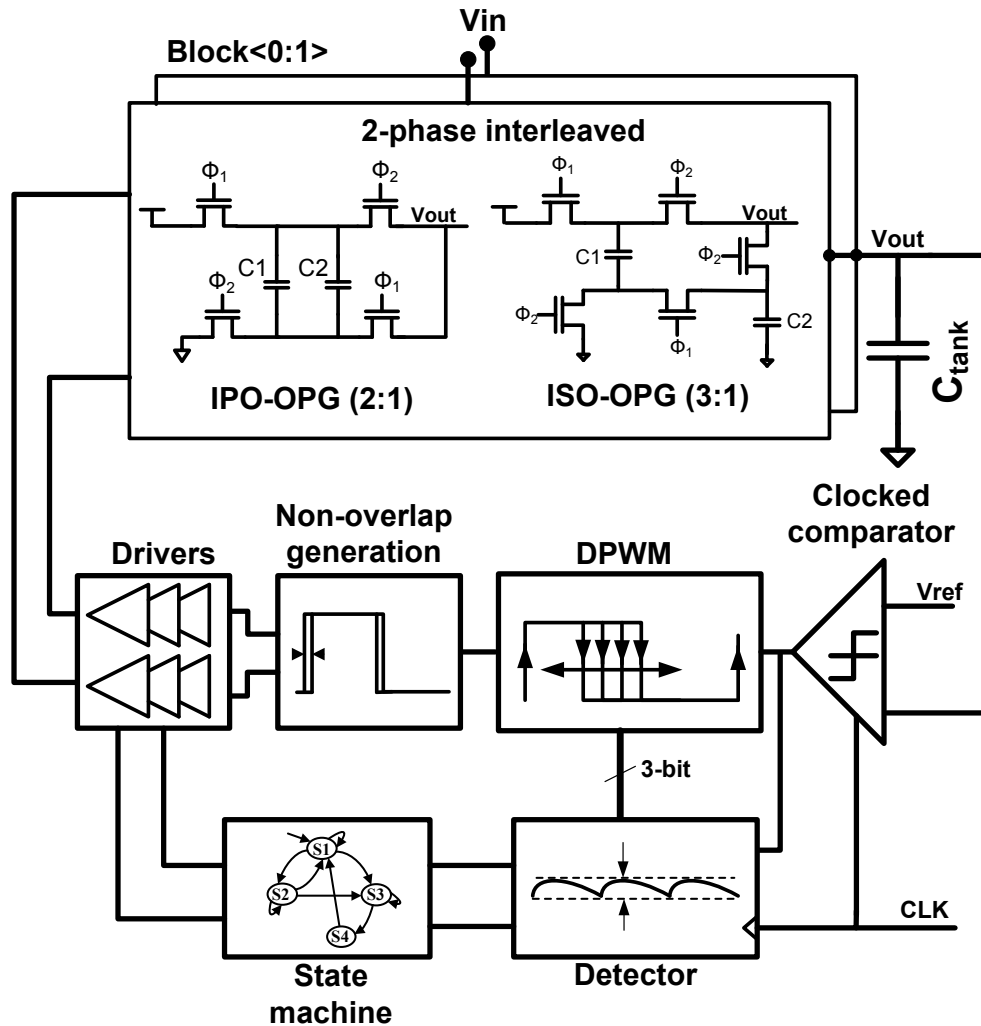
Regulation



- Single bound hysteretic control \rightarrow regulation
- Clk freq = 200MHz
- Two copies of the converter core block
- # of blocks operational decided by state machine

- Converter \rightarrow 2 phase interleaved
- Two modes
 - ISO-OPG (3:1)
 - IPO-OPG (2:1)
- Same bucket caps used in both modes

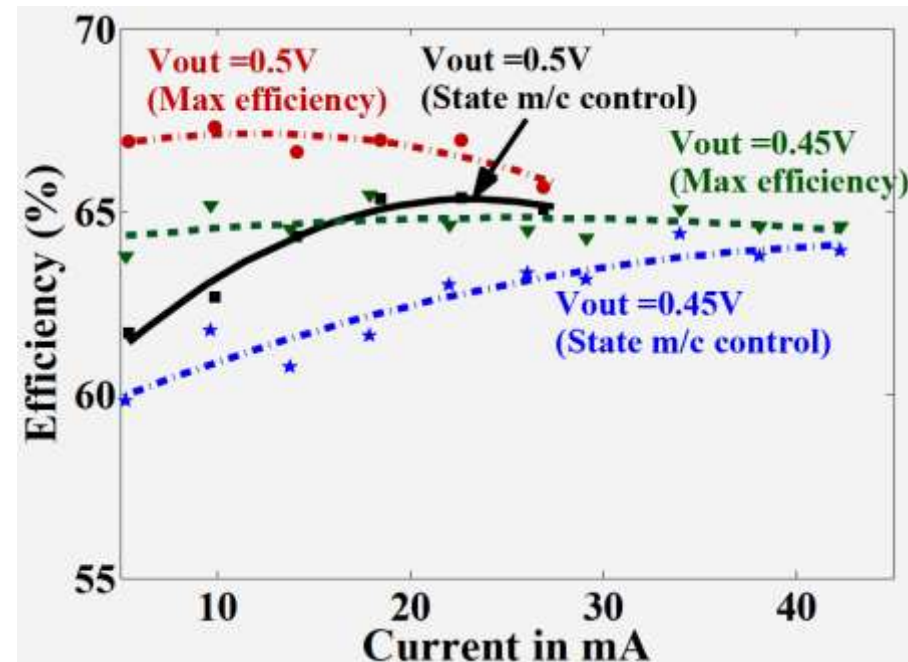
Fully Integrated Converter



- Input to secondary loop
 - Primary switching frequency
- Capacitance modulation
 - All caps switching
 - Half of caps switching
- Pulse width \rightarrow 3 bits
- Interaction between primary and secondary loop

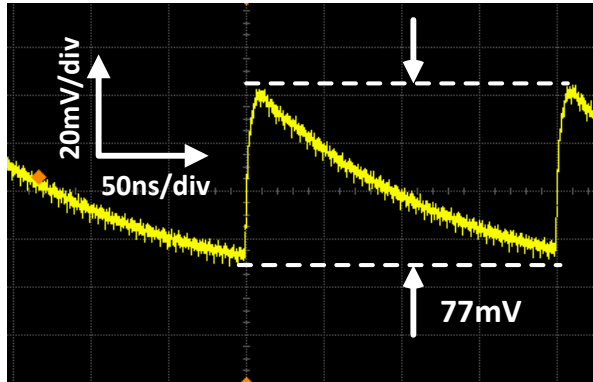
Measurement Results (I)

- Max efficiency mode → all bucket caps switching
- State machine control
 - Based on ripple selects mode
 - Lower efficiency → higher frequency
 - Less ripple (next slide)
- Experiment
 - Load current varied @ different V_{out}
 - Manual control (no S/M control)
 - With state machine control

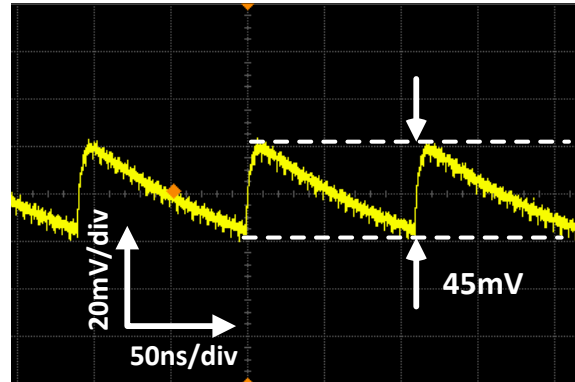


Measurement Results (V)

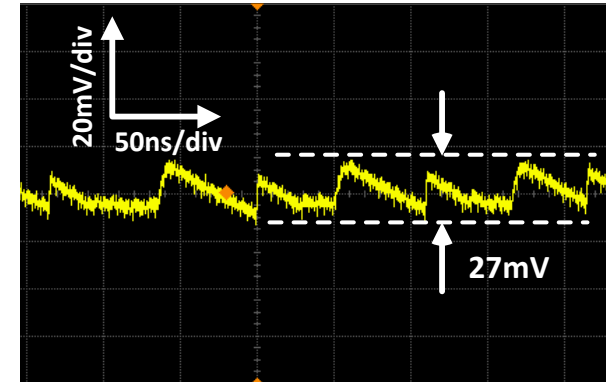
Full capacitance switching



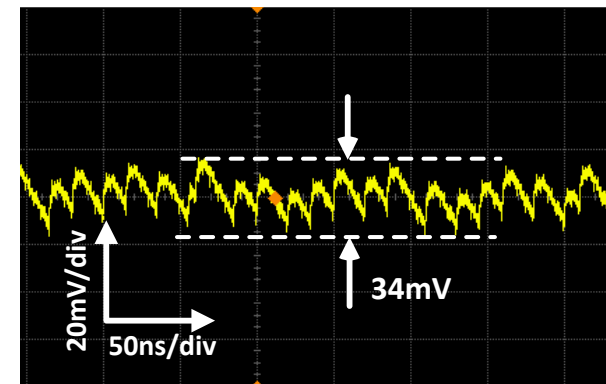
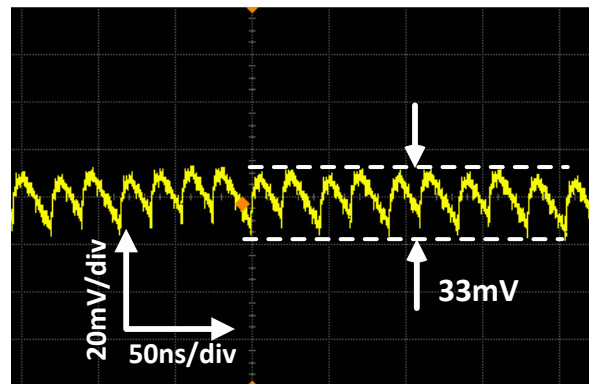
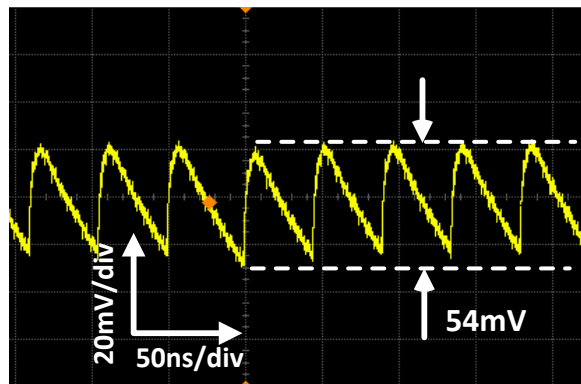
Capacitance modulation



Capacitance + Pulse width (State m/c control)



$$V_{\text{out}} = 0.4\text{V} \quad I_{\text{load}} = 2\text{mA}$$



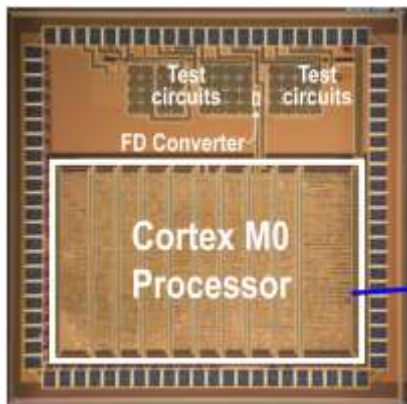
$$V_{\text{out}} = 0.45\text{V} \quad I_{\text{load}} = 7.33\text{mA}$$

Comparison With Prior Work

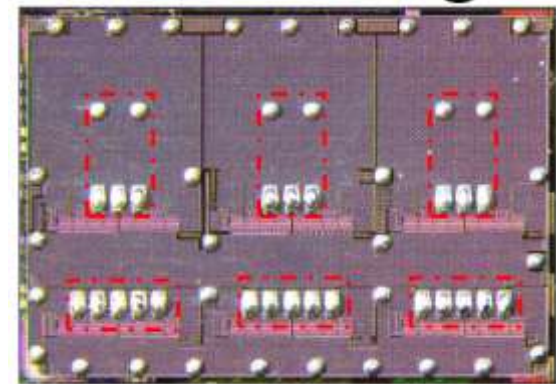
- Achieves efficiency comparable to designs in lower tech. nodes
- Efficiency expected to increase with technology scaling

Work	Technology	Design technique	Max efficiency	Comments
[Lee07]	600nm	Resistance modulation	87%	Off-chip capacitors
[Le11]	32nm	32-phase interleaved	80%	Fully integrated
[Ramadass10]	45nm	Capacitance modulation	69%	Fully integrated
This work	130nm	Cap + time modulation	70%	Fully integrated

SPECIAL CAPACITIVE CONVERTERS



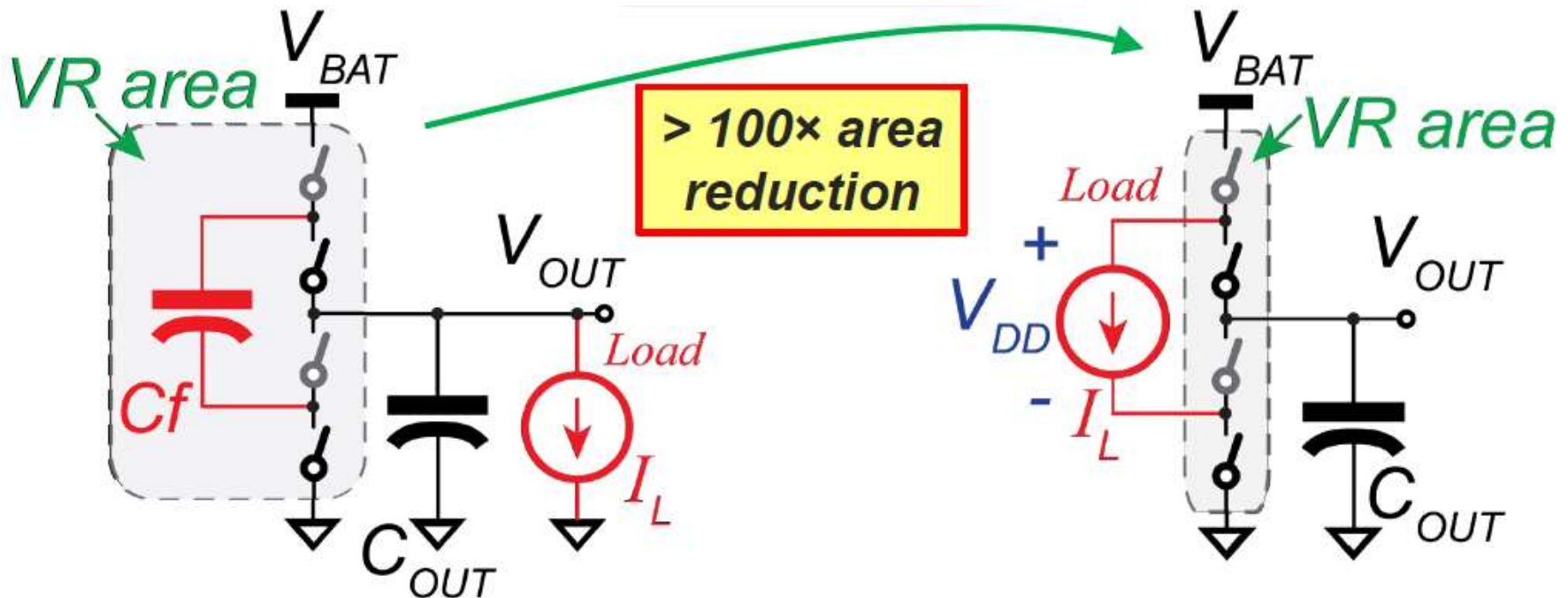
Flying Domain SC DC-DC
Process: 180nm SOI
Loai G. Salem, ISSCC 2016



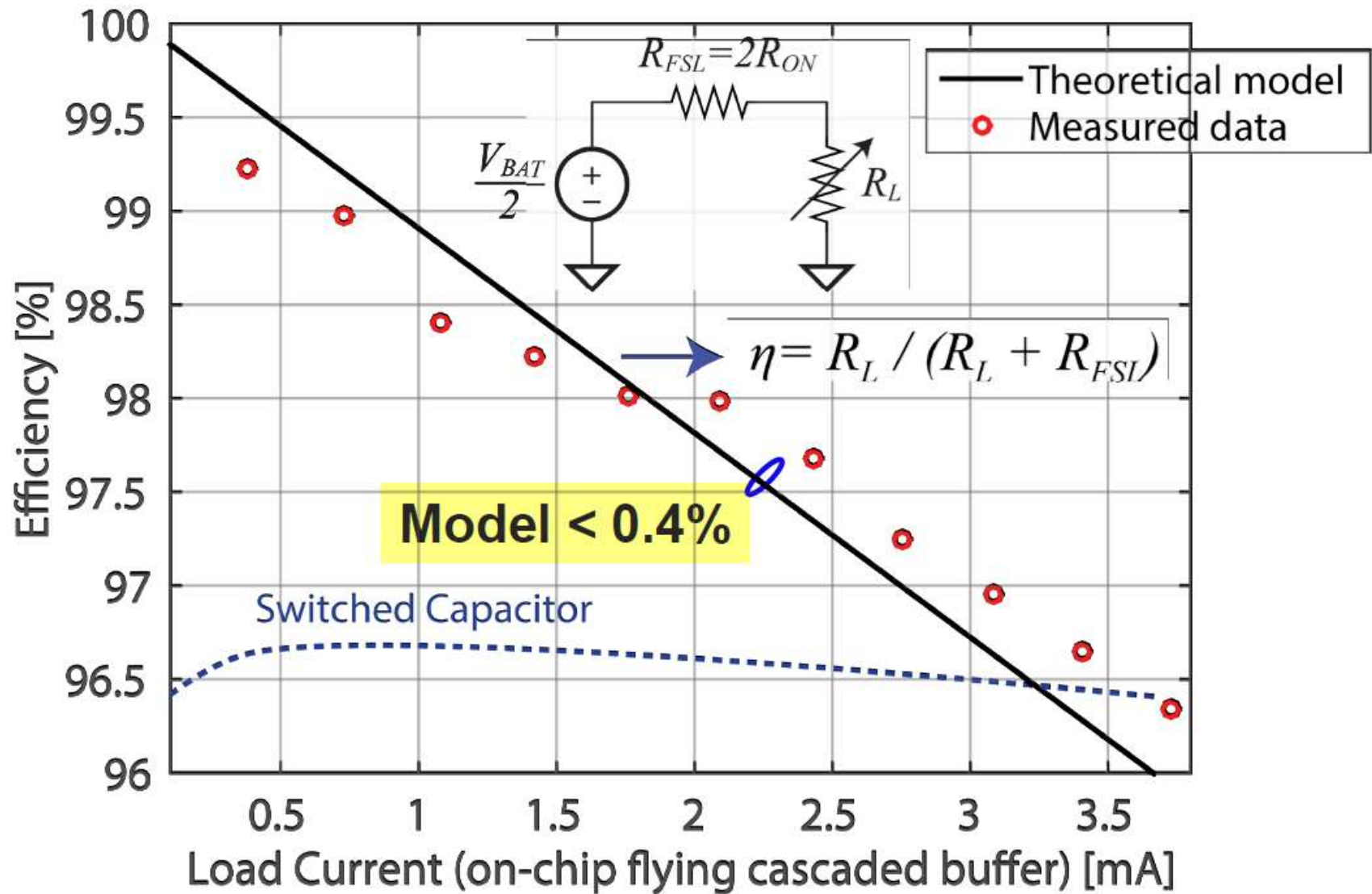
Resonant SC DC-DC
C. Schaef, ISSCC 2015

Flying Domain DC-DC Converter

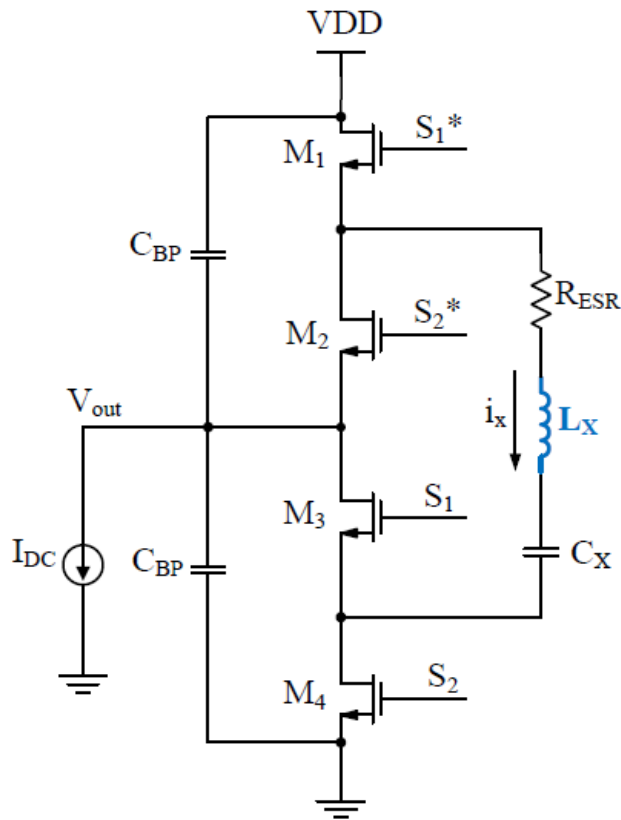
- Flying domain DC-DC converter
- Interchange the bucket capacitor with load
- 100X area reduction, no parasitic loss
- Requires SOI



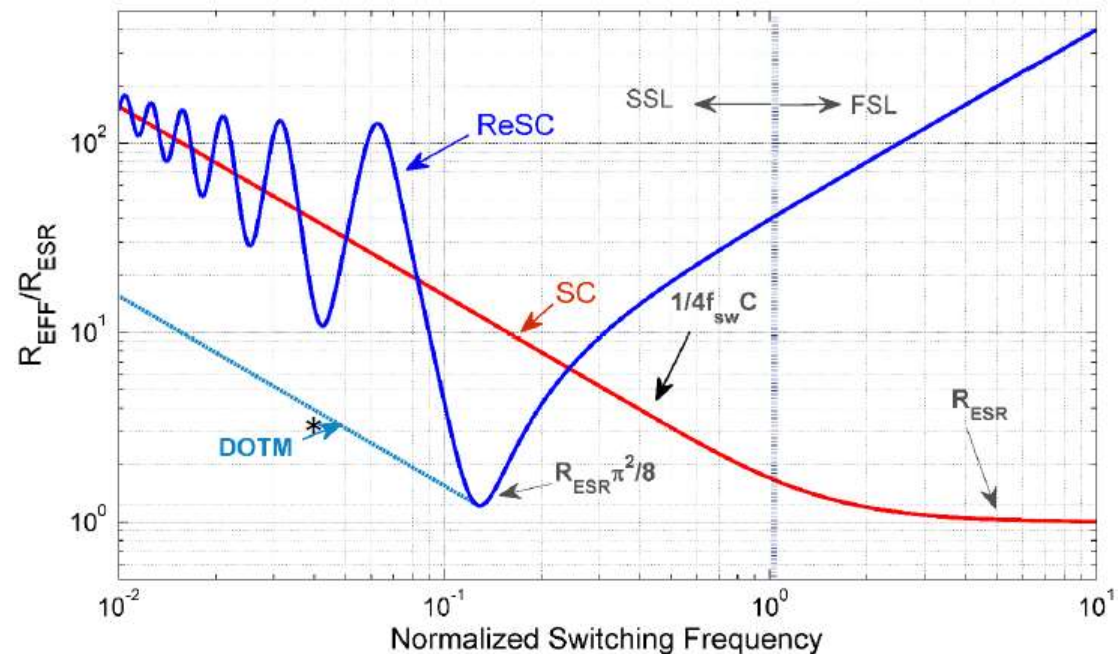
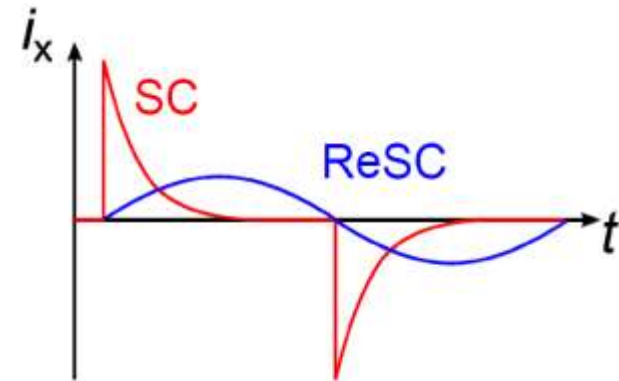
Efficiency Measurement



Resonant Capacitive Converters



2:1 ReSC DC-DC



Conclusions

- Linear converters
 - 1:1 conversion ratio, series/shunt
 - Easy to implement
 - LDOs vs DLDOs (for lower supply voltages)
- Inductive converters
 - Theoretical 100% efficiency
 - Integrated inductors are problem. Low quality factor
- Capacitive converters
 - Series parallel design framework
 - Capacitive and frequency based output regulation
- Special capacitive converters
 - Flying domain
 - Resonant converters



Questions

